

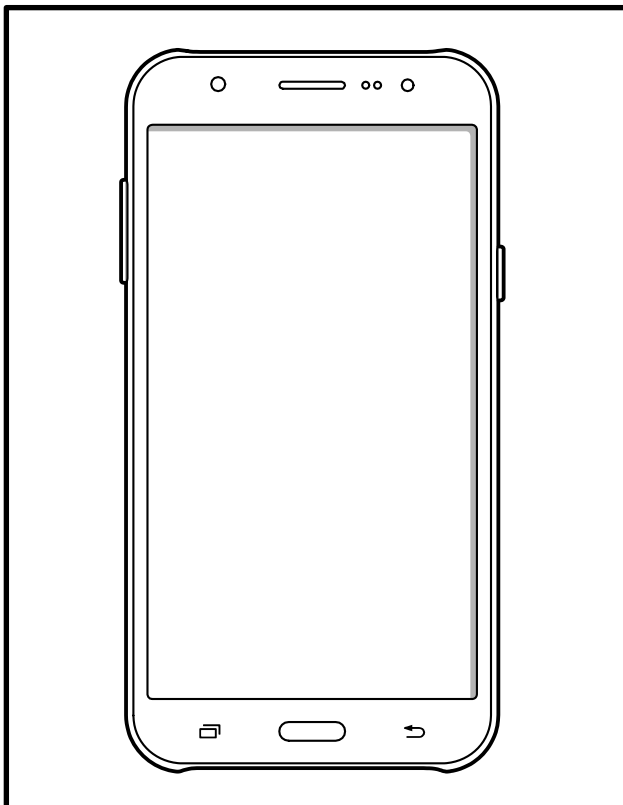
**SAMSUNG**

# Wireless Device

## SM-J700F

# ***SERVICE*** *Manual*

### Wireless Device



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Notice: All functionality, features, specifications, and other product information provided in this document, including but not limited to, benefits, design, pricing, components, performance, availability, and capabilities of the product are subject to change without notice. Samsung reserves the right to alter this document or the product described herein at anytime, without obligation to provide notification of such changes.

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# 1. Safety Precautions

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## 1-1. Repair Precaution

Before attempting any repair or detailed tuning, shield the device from RF noise or static electricity discharges.

Use only demagnetized tools that are specifically designed for small electronic repairs, as most electronic parts are sensitive to electromagnetic forces.

Use only high quality screwdrivers when servicing products. Low quality screwdrivers can easily damage the heads of screws.

Use only conductor wire of the properly gauge and insulation for low resistance, because of the low margin of error of most testing equipment.

We recommend 22-gauge twisted copper wire.

Hand-soldering is not recommended, because printed circuit boards (PCBs) can be easily damaged, even with relatively low heat. Never use a soldering iron with a power rating of more than 100 watts and use only lead-free solder with a melting point below 250°C (482°F).

Prior to disassembling the battery charger for repair, ensure that the AC power is disconnected. Always use the replacement parts that are registered in the SEC system. Third-party replacement parts may not function properly.

## **1-2. ESD(Electrostatically Sensitive Devices) Precaution**

Many semiconductors and ESDs in electronic devices are particularly sensitive to static discharge and can be easily damaged by it. We recommend protecting these components with conductive anti-static bags when you store or transport them.

Always use an anti-static strap or wristband and remove electrostatic buildup or dissipate static electricity from your body before repairing ESDs.

Ensure that soldering irons have AC adapter with ground wires and that the ground wires are properly connected.

Use only desoldering tools with plastic tips to prevent static discharge.

Properly shield the work environment from accidental electrostatic discharge before opening packages containing ESDs.

The potential for static electricity discharge may be increased in low humidity environments, such as air-conditioned rooms. Increase the airflow to the working area to decrease the chance of accidental static electricity discharges.

## 2. Specification

### 2-1. GSM General Specification

	GSM850	EGSM 900	DCS1800	PCS1900	WCDMA 2100	WCDMA 1900	WCDMA 900	WCDMA 850
Freq. Band[MHz] Uplink/ Downlink	824~849 869~894	880~915 925~960	1710~1785 1805~1880	1850~1910 1930~1990	1922~1977 2110~2170	1852~1907 1932~1987	880~915 925~960	824~849 869~894
ARFCN range	128~251	0~124 & 975~1023	512~885	512~810	UL:9612~9888 DL:10562~10838	UL:9262~9538 DL:9662~9938	UL: 2712~2863 DL: 2937~3088	UL: 4132~4233 DL: 4357~4458
Tx/Rx spacing	45MHz	45MHz	95MHz	80MHz	190MHz	80MHz	45MHz	45MHz
Mod. Bit rate/ Bit Period	270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us	270.833kbps 3.692us	3.84Mcps	3.84Mcps	3.84Mcps	3.84Mcps
Time Slot Period/ Frame Period	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	576.9us 4.615ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms	FrameLength: 10ms Slotlength: 0.667ms
Modulation	0.3GMSK	0.3GMSK	0.3GMSK	0.3GMSK	QPSK, HPSK	QPSK, HPSK	QPSKHQPSK	QPSKHQPSK
MS Power	33dBm~5dBm	33dBm~5dBm	30dBm~0dBm	30dBm~0dBm	24dBm~-50dBm	24dBm~-50dBm	24dBm~-50dBm	24dBm~-50dBm
Power Class	5pcl ~ 19pcl	5pcl ~ 19pcl	0pcl ~ 15pcl	0pcl ~ 15pcl	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)	3(max+24dBm)
Sensitivity	-102dBm	-102dBm	-100dBm	-100dBm	-106.7dBm	-106.7dBm	-106.7dBm	-106.7dBm
TDMA Mux	8	8	8	8	8	8	8	8
Cell Radius	35Km	35Km	2Km	2Km	2Km	2Km	2Km	2Km

## 2-2. GSM Tx Power Class

<b>TX Power control level</b>	<b>GSM850</b>	<b>TX Power control level</b>	<b>EGSM900</b>	<b>TX Power control level</b>	<b>DCS1800</b>	<b>TX Power control level</b>	<b>PCS1900</b>
5	33±2 dBm	5	33±2 dBm	0	30±3 dBm	0	30±3 dBm
6	31±2 dBm	6	31±2 dBm	1	28±3 dBm	1	28±3 dBm
7	29±2 dBm	7	29±2 dBm	2	26±3 dBm	2	26±3 dBm
8	27±2 dBm	8	27±2 dBm	3	24±3 dBm	3	24±3 dBm
9	25±2 dBm	9	25±2 dBm	4	22±3 dBm	4	22±3 dBm
10	23±2 dBm	10	23±2 dBm	5	20±3 dBm	5	20±3 dBm
11	21±2 dBm	11	21±2 dBm	6	18±3 dBm	6	18±3 dBm
12	19±2 dBm	12	19±2 dBm	7	16±3 dBm	7	16±3 dBm
13	17±2 dBm	13	17±2 dBm	8	14±3 dBm	8	14±3 dBm
14	15±2 dBm	14	15±2 dBm	9	12±4 dBm	9	12±4 dBm
15	13±2 dBm	15	13±2 dBm	10	10±4 dBm	10	10±4 dBm
16	11±3 dBm	16	11±3 dBm	11	8±4 dBm	11	8±4 dBm
17	9±3dBm	17	9±3dBm	12	6±4 dBm	12	6±4 dBm
18	7±3 dBm	18	7±3 dBm	13	4±4 dBm	13	4±4 dBm
19	5±3 dBm	19	5±3 dBm	14	2±5 dBm	14	2±5 dBm
				15	0±5 dBm	15	0±5 dBm

## 2-3. LTE General Specification

	LTE Band1	LTE Band3	LTE Band5	LTE Band7	LTE Band8	LTE Band20
Freq. Band[MHz] Uplink/ Downlink	1920~1980 2110~2170	1710~1785 1805~1880	824~849 869~894	2500~2570 2620~2690	880~915 925~960	832~862 791~821
ARFCN range	UL: 18000~18599 DL: 0~599	UL: 19200~19949 DL: 1200~1949	UL: 20400~20649 DL: 2400~2649	UL: 20750~21449 DL: 2750~3449	UL: 21450~21799 DL: 3450~3799	UL: 24150~24449 DL: 6150~6449
Tx/Rx spacing	190MHz	95MHz	45MHz	120MHz	45MHz	-41MHz
Channel Bandwidth	5/10/15/20 MHz	1.4/3/5/10/15/20 MHz	1.4/3/5/10 MHz	5/10/15/20 MHz	1.4/3/5/10MHz	5/10/15/20 MHz
Modulation	QPSK,16/64QAM	QPSK,16/64QAM	QPSK,16/64QAM	QPSK,16/64QAM	QPSK,16/64QAM	QPSK,16/64QAM
MS Power (MPR)	-35~25.7 dBm	-35~25.7 dBm	-35~25.7 dBm	-35~25.7 dBm	-35~25.7 dBm	-35~25.7 dBm
Sensitivit (QPSK) (BW 10MHz)	-97dBm	-94dBm	-95dBm	-95dBm	-94dBm	-94dBm
Cell Radius	>5Km	>5Km	>5Km	>5Km	>5Km	>5Km

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## 3. Operation Instruction and Installation

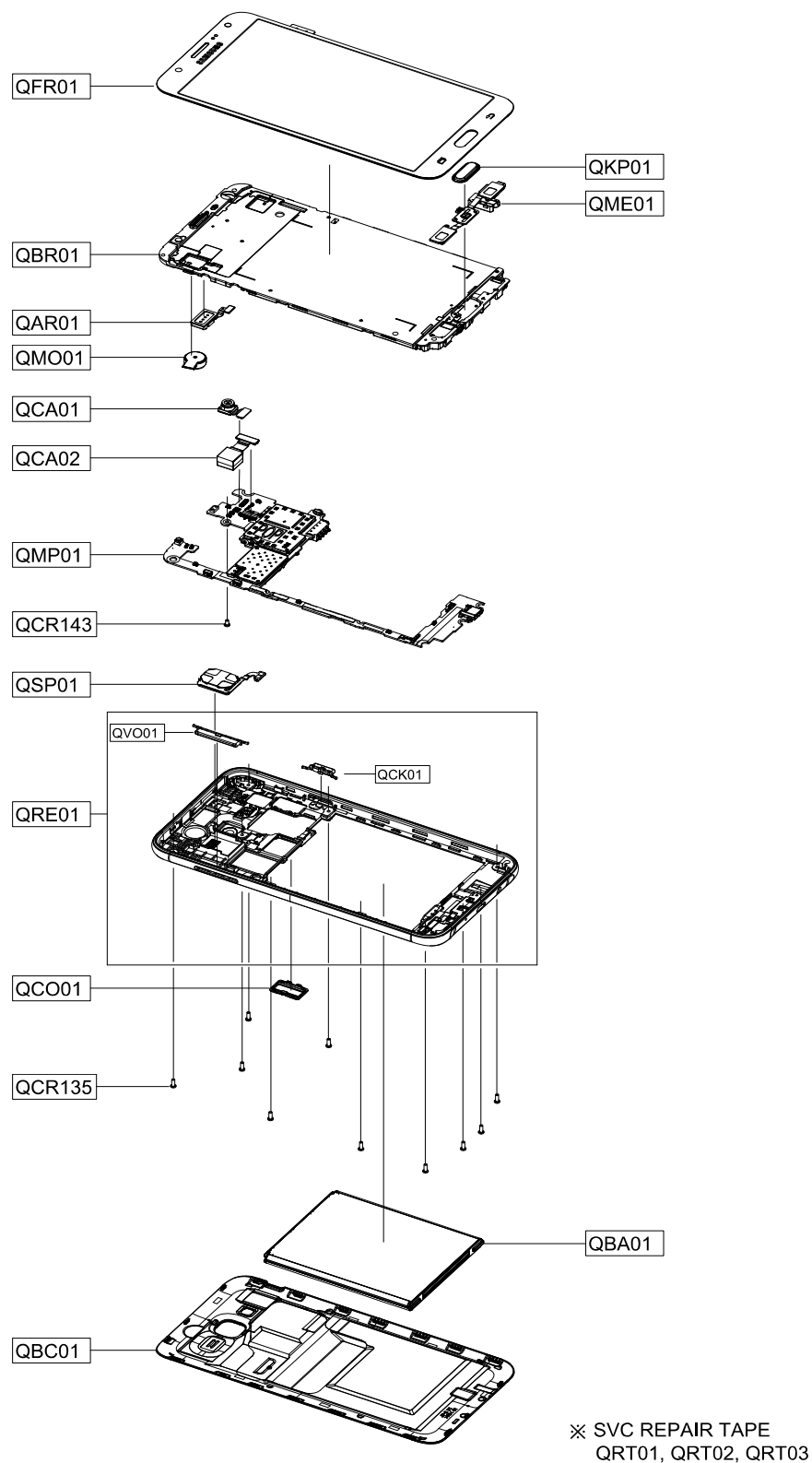
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### Main Function

Item	Description
OS	Android V5.1 (Lollipop)
RF	LTE Cat.4 (150/50Mbps)
Battery	3,000mAh
Base Band	1.5GHz OCTA
Other RF	GPS, Glonass, Beidou, BT4.1, USB 2.0, WIFI 802.11 b/g/n
Camera	13MP Main CAM 5MP(Front)
LCD	5.5" OCTA HD, 720 x 1280
RAM	1.5GB RAM + 16GB eMMC
Sensor	Accelerometer, Proximity, Hall IC
Accessory	Charger: 5V/1.5A Data cable: 3.3pi, 1.0m Ear phone: 3.5pi, 4pin

## 4. Exploded View and Parts List

### 4-1. Cellular phone Exploded View





## 4-2. Cellular phone Parts list

Design LOC		Description	SEC CODE
QCR135		SCREW-MACHINE	6001-003113
QCO01		COVER-LCD_CAP	GH63-11081A
QMP01		A/S ASSY-PBA MAIN(COMM)SM_J700F/DS	GH82-10220A
QCA01		ASSY CAMERA-5M(SM-J700F)	GH96-08703A
QCA02		ASSY CAMERA-MODULE_13M CAM_1/3.6"_SM-J70	GH96-08734A
QCR143		SCREW-MACHINE	6001-003180
QAR01		AUDIO-RECEIVER	3009-001693
QMO01		MOTOR LINEAR VIBRATION-SM_J700F	GH31-00729A
QBR01		ASSY BRACKET-EU	GH98-37385A
QBA01		INNER BATTERY PACK-EB-BJ700CBE,3000MAH,U	GH43-04530A
QBC01		ASSY COVER-BATT(EU)	GH98-37384A
QSP01		MICRO SPEAKER	3001-002816
QRE01		ASSY CASE-REAR(EU)	GH98-37383A
	QCK01	KEY-POWER	GH64-04963A
	QVO01	KEY-VOLUME	GH64-04964A
QKP01		ASSY KEY-HOME	GH98-37591A
QME01		ASSY MODULE-TOUCH KEY(SM_J700F)	GH96-08865A
QFR01		SVC LCD ASSY-SM_J700F(E/WHITE)	GH97-17670A
QRT01		A/S-TAPE OCTA-REWORK	GH81-13061A
QRT02		A/S-TAPE OCTA CU SHEET_REWORK	GH81-13096A
QRT03		A/S-DOUBLE TAPE ASS'Y 2	GH81-13109A

## 5. MAIN Electrical Parts List

Design LOC	SEC CODE	Description
ZD5008	0401-001110	DIODE-SWITCHING
ZD5001,ZD5004,ZD5005	0406-001223	DIODE-TVS
ZD5010,ZD5011,ZD5012	0406-001223	DIODE-TVS
ZD6003	0406-001223	DIODE-TVS
ZD5009	0406-001413	DIODE-TVS
ZD4002	0406-001459	DIODE-TVS
ZD6000,ZD6001,ZD6002	0406-001568	DIODE-TVS
ZD6004,ZD6005	0406-001568	DIODE-TVS
ZD5006,ZD5007	0406-001592	DIODE-TVS
ZD5002,ZD5003	0406-001645	DIODE-TVS
ZD4000	0406-001675	DIODE-TVS
ZD4003,ZD4004	0406-001687	DIODE-TVS
ZD4001	0406-001694	DIODE-TVS
LED4000	0601-003511	LED
LED6000	0601-003547	LED
U4003	1001-001650	IC
U1013	1001-001912	IC
U5000	1001-001928	IC
U1031	1001-001972	IC
U6002	1009-001066	IC
UME4000	1107-002373	MEMORY
U2010	1201-003783	IC
PAM1001	1201-003812	IC
PAM1000	1201-003968	IC
U6000	1203-007884	IC
U4005	1203-008250	IC
U1026	1203-008288	IC
U6001	1203-008527	IC
U4004	1203-008539	IC
U4002	1203-008574	IC
U2009	1205-005220	IC
U2011	1205-005310	IC
U4009	1205-005315	IC
UCP300	1205-005344	IC
U1045	1205-005272	IC
U1043	1209-002043	IC

U6003	1209-002275	IC
U6004	1209-002335	IC
TH1000,TH3000,TH3001	1404-001724	THERMISTOR
VR6000,VR6001	1405-001390	IC
R6066	2007-000140	R-CHIP
R4032	2007-000172	R-CHIP
R5025	2007-007137	R-CHIP
R3043	2007-007315	R-CHIP
R5026	2007-007585	R-CHIP
R5027	2007-007942	R-CHIP
R1011	2007-008043	R-CHIP
R2007,R5014,R5015	2007-008055	R-CHIP
R5017,R5028,R6068	2007-008055	R-CHIP
R1008,R1009	2007-008056	R-CHIP
R6003	2007-008137	R-CHIP
R6027	2007-008210	R-CHIP
R4016	2007-008211	R-CHIP
R5030	2007-008354	R-CHIP
R3030,R3031,R4029	2007-008419	R-CHIP
R6024,R6025,R6026	2007-008483	R-CHIP
R6065	2007-008483	R-CHIP
R3013,R4010,R4012	2007-008486	R-CHIP
R4013,R4018,R5022	2007-008486	R-CHIP
R2002,R3002,R3006	2007-008516	R-CHIP
R3008,R3009,R3010	2007-008516	R-CHIP
R3011,R3012,R3036	2007-008516	R-CHIP
R4006,R4009,R4017	2007-008516	R-CHIP
R5002,R5004,R5016	2007-008516	R-CHIP
R6000,R6002,R6018	2007-008516	R-CHIP
R6001	2007-008531	R-CHIP
R1007,R2014	2007-008587	R-CHIP
R3018,R3019,R3020	2007-008588	R-CHIP
R3021,R3022,R3023	2007-008588	R-CHIP
R3024,R3025,R3026	2007-008588	R-CHIP
R3027,R3028,R3029	2007-008588	R-CHIP
R3055,R3056,R6007	2007-008588	R-CHIP
R6022	2007-008588	R-CHIP

R4028,R4030	2007-008774	R-CHIP
R1006	2007-008785	R-CHIP
R4011	2007-008798	R-CHIP
R3039,R3042,R3047	2007-008800	R-CHIP
R3048,R3050,R3052	2007-008800	R-CHIP
R1001	2007-008806	R-CHIP
R2001,R4008	2007-009111	R-CHIP
R1003,R3040,R3041	2007-009157	R-CHIP
R3054	2007-009158	R-CHIP
R3016,R3017,R4007	2007-009171	R-CHIP
R5023	2007-009171	R-CHIP
R4000,R5024	2007-009212	R-CHIP
R3053	2007-009223	R-CHIP
R5029	2007-009233	R-CHIP
R4037	2007-009315	R-CHIP
R3014	2007-009398	R-CHIP
R5005,R5007	2007-009766	R-CHIP
R3037,R3049,R3051	2007-009920	R-CHIP
R3015	2007-011043	R-CHIP
R4025	2007-011648	R-CHIP
R415	2007-012068	R-CHIP
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C1015	2203-000278	C-CERAMIC,CHIP
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C4117	2203-005344	C-CERAMIC,CHIP
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C4126	2203-005725	C-CERAMIC,CHIP
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C4115	2203-005732	C-CERAMIC,CHIP

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C3011,C3012,C3015	2203-007449	C-CERAMIC,CHIP
C3016,C3019,C3024	2203-007449	C-CERAMIC,CHIP
C3025,C3026,C3028	2203-007449	C-CERAMIC,CHIP
C3029,C3030,C3031	2203-007449	C-CERAMIC,CHIP
C3032,C3035,C3036	2203-007449	C-CERAMIC,CHIP
C3037,C3038,C3039	2203-007449	C-CERAMIC,CHIP
C3041,C3042,C3044	2203-007449	C-CERAMIC,CHIP
C3059,C3060,C3061	2203-007449	C-CERAMIC,CHIP
C3069,C3070,C3074	2203-007449	C-CERAMIC,CHIP
C3079,C3083,C4000	2203-007449	C-CERAMIC,CHIP
C4009,C4010,C4011	2203-007449	C-CERAMIC,CHIP
C4012,C4013,C4014	2203-007449	C-CERAMIC,CHIP
C4015,C4016,C4017	2203-007449	C-CERAMIC,CHIP
C4033,C4043,C4044	2203-007449	C-CERAMIC,CHIP
C4050,C4051,C4052	2203-007449	C-CERAMIC,CHIP
C4057,C4060,C4073	2203-007449	C-CERAMIC,CHIP
C4079,C4082,C4102	2203-007449	C-CERAMIC,CHIP

C4103,C4119,C6007	2203-007449	C-CERAMIC,CHIP
C6008,C6009,C6013	2203-007449	C-CERAMIC,CHIP
C6027,C6060,C6086	2203-007449	C-CERAMIC,CHIP
C3000,C3013,C3020	2203-007474	C-CERAMIC,CHIP
C3033,C4020,C4028	2203-007474	C-CERAMIC,CHIP
C4037,C4062,C4067	2203-007474	C-CERAMIC,CHIP
C4069,C4071,C4075	2203-007474	C-CERAMIC,CHIP
C4080,C4122,C4123	2203-007474	C-CERAMIC,CHIP
C4127	2203-007474	C-CERAMIC,CHIP
C6004	2203-007775	C-CERAMIC,CHIP
C6062,C6064,C6066	2203-007781	C-CERAMIC,CHIP
C6087	2203-007781	C-CERAMIC,CHIP
C1011,C1094,C1100	2203-007795	C-CERAMIC,CHIP
C1104,C1111,C4064	2203-007795	C-CERAMIC,CHIP
C6063	2203-007795	C-CERAMIC,CHIP
C3021,C3045,C3084	2203-007796	C-CERAMIC,CHIP
C3085,C3086,C4035	2203-007796	C-CERAMIC,CHIP
C4081,C4084,C5030	2203-007796	C-CERAMIC,CHIP
C6006,C6010,C6011	2203-007796	C-CERAMIC,CHIP
C3001,C3014,C3018	2203-008242	C-CERAMIC,CHIP
C3023,C4003,C4004	2203-008242	C-CERAMIC,CHIP
C4045,C4047,C4048	2203-008242	C-CERAMIC,CHIP
C4059,C4104,C5009	2203-008242	C-CERAMIC,CHIP
C6028	2203-008242	C-CERAMIC,CHIP
C4109,C4116	2203-008654	C-CERAMIC,CHIP
C4105	2203-008794	C-CERAMIC,CHIP
L1003	2703-002267	INDUCTOR-SMD
L1005	2703-002268	INDUCTOR-SMD
L1042,L2010	2703-002649	INDUCTOR-SMD
C1045,L1065,L1070	2703-002858	INDUCTOR-SMD
L1071	2703-002858	INDUCTOR-SMD
C1040	2703-002903	INDUCTOR-SMD
L1014	2703-002955	INDUCTOR-SMD
L5011	2703-002959	INDUCTOR-SMD
L2003,L5014	2703-002960	INDUCTOR-SMD
L1064	2703-002999	INDUCTOR-SMD
L4011	2703-003686	INDUCTOR-SMD



L5008	2703-003878	INDUCTOR-SMD
L1008	2703-004000	INDUCTOR-SMD
C1076,L1021	2703-004013	INDUCTOR-SMD
L1011,L1022,L1043	2703-004018	INDUCTOR-SMD
C1048,L1009,L1012	2703-004032	INDUCTOR-SMD
L1034,L2002	2703-004032	INDUCTOR-SMD
C1022,C1025,C1062	2703-004034	INDUCTOR-SMD
C1005,L1049,L1063	2703-004035	INDUCTOR-SMD
C1099,L1026,L1050	2703-004037	INDUCTOR-SMD
L1060	2703-004037	INDUCTOR-SMD
C1021,L1000	2703-004287	INDUCTOR-SMD
L2012	2703-004288	INDUCTOR-SMD
C1007,C1019	2703-004289	INDUCTOR-SMD
L6001	2703-004297	INDUCTOR-SMD
L2013	2703-004301	INDUCTOR-SMD
C1078,L2000	2703-004328	INDUCTOR-SMD
L2009	2703-004362	INDUCTOR-SMD
C1077,L1031,L1062	2703-004364	INDUCTOR-SMD
L1067	2703-004367	INDUCTOR-SMD
L1053	2703-004368	INDUCTOR-SMD
C1034,C1047,C1145	2703-004408	INDUCTOR-SMD
L1061	2703-004408	INDUCTOR-SMD
L2014	2703-004763	INDUCTOR-SMD
C1049	2703-004764	INDUCTOR-SMD
L4002,L4003,L4004	2703-004901	INDUCTOR-SMD
L4005,L4006,L4007	2703-004901	INDUCTOR-SMD
L4008	2703-004901	INDUCTOR-SMD
L2005	2703-004914	INDUCTOR-SMD
L4012	2703-004947	INDUCTOR-SMD
L1019,L1051,L1055	2703-004976	INDUCTOR-SMD
L1058	2703-004976	INDUCTOR-SMD
L1028	2703-005106	INDUCTOR-SMD
L6018	2703-005108	INDUCTOR-SMD
L6013,L6016	2703-005117	INDUCTOR-SMD
OSC2000	2801-005167	CRYSTAL-UNIT
OSC4000	2801-005254	CRYSTAL-UNIT
OSC2001	2805-001116	CRYSTAL-UNIT

OSC1000	2809-001417	CRYSTAL-UNIT
F6004,F6005	2901-001673	Filter EMI
F6000,F6001,F6002	2901-001674	Filter EMI
F6003	2901-001674	Filter EMI
F2001	2904-002168	FILTER-SAW
F1004	2904-002227	FILTER-SAW
F1006	2904-002257	FILTER-SAW
F1005	2904-002269	FILTER-SAW
F1002	2904-002302	FILTER-SAW
F2000	2904-002314	FILTER-SAW
U1025	2910-000253	FILTER
U1044	2911-000377	FILTER
U1019	2911-000381	FILTER
MIC5000	3003-001215	MIC-CONDENSOR
L5016	3301-001729	CORE-FERRITE BEAD
L6015,L6017,L6019	3301-001789	CORE-FERRITE BEAD
L6009	3301-001812	CORE-FERRITE BEAD
L2008	3301-001876	CORE-FERRITE BEAD
L5017	3301-001885	CORE-FERRITE BEAD
L1010,L2004,L2007	3301-001895	CORE-FERRITE BEAD
L5002,L5007	3301-001901	CORE-FERRITE BEAD
L5004	3301-001917	CORE-FERRITE BEAD
L2006	3301-002074	CORE-FERRITE BEAD
L5003,L5005,L5006	3301-002078	CORE-FERRITE BEAD
L5009,L5010	3301-002085	CORE-FERRITE BEAD
L1068	3301-002122	CORE-FERRITE BEAD
L5012,L5013,L6010	3301-002236	CORE-FERRITE BEAD
L6020,L6021	3301-002236	CORE-FERRITE BEAD
L1045,L1046	3301-002248	CORE-FERRITE BEAD
L4009	3301-002254	CORE-FERRITE BEAD
L1048	3301-002312	CORE-FERRITE BEAD
TAC5000,TAC5001	3404-001550	SWITCH-TACT
TAC5002	3404-001550	SWITCH-TACT
RFS1000	3705-001708	CONNECTOR-COAXIAL
SIM6000	3709-001799	CONNECTOR-CARD EDGE
SIM6001	3709-001863	CONNECTOR-CARD EDGE
HDC6000	3711-007295	CONNECTOR-HEADER

HDC6001	3711-007617	CONNECTOR-HEADER
HDC5000	3711-007810	CONNECTOR-HEADER
HDC6002	3711-008511	CONNECTOR-HEADER
BTC4000	3711-008737	CONNECTOR-HEADER
ANT2000	3712-001516	CONNECTOR
ANT5002,ANT5003	3712-001604	CONNECTOR
ANT1000,ANT1001	3712-001621	CONNECTOR
ANT1002,ANT2001	3712-001621	CONNECTOR
ANT5000,ANT5001	3712-001621	CONNECTOR
ANT5004,ANT5005	3712-001621	CONNECTOR
IFC4000	3722-003708	JACK-PHONE
U1011	4709-002193	RF-MODULE
SUS1000	GH61-08265A	SUS
SUS1001	GH61-09617A	SUS
SUS1002	GH61-09781A	SUS
SMR1001,SMR1002	GH62-00040A	JSM
SMR6002,SMR6003	GH62-00040A	JSM
SMR6004,SMR6005	GH62-00040A	JSM
SMR6006,SMR6007	GH62-00040A	JSM
SMR6001	GH62-00042A	JSM
SC1000	GH63-09457A	SHIELD-CAN
SC2000	GH63-10991A	SHIELD-CAN
SC2002	GH98-37386A	SHIELD-CAN
SC1001	GH98-37592A	SHIELD-CAN
SC2001	GH98-37593A	SHIELD-CAN
UCP300UP	1105-002606	MEMORY

Please consult the GSPN website (Samsung Portal) for the most recent version of the product's part list.

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## 6. Level 1 Repair

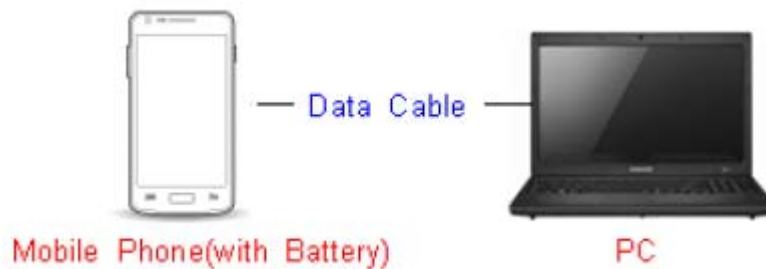
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### 6-1. S/W installation

#### 6-1-1. Required items in order to install S/W

- Installation program: Downloader Program (**Odin3 v3.10.6.exe**)
- Mobile Phone
- Data Cable
- Mobile device specific S/W: Binary files

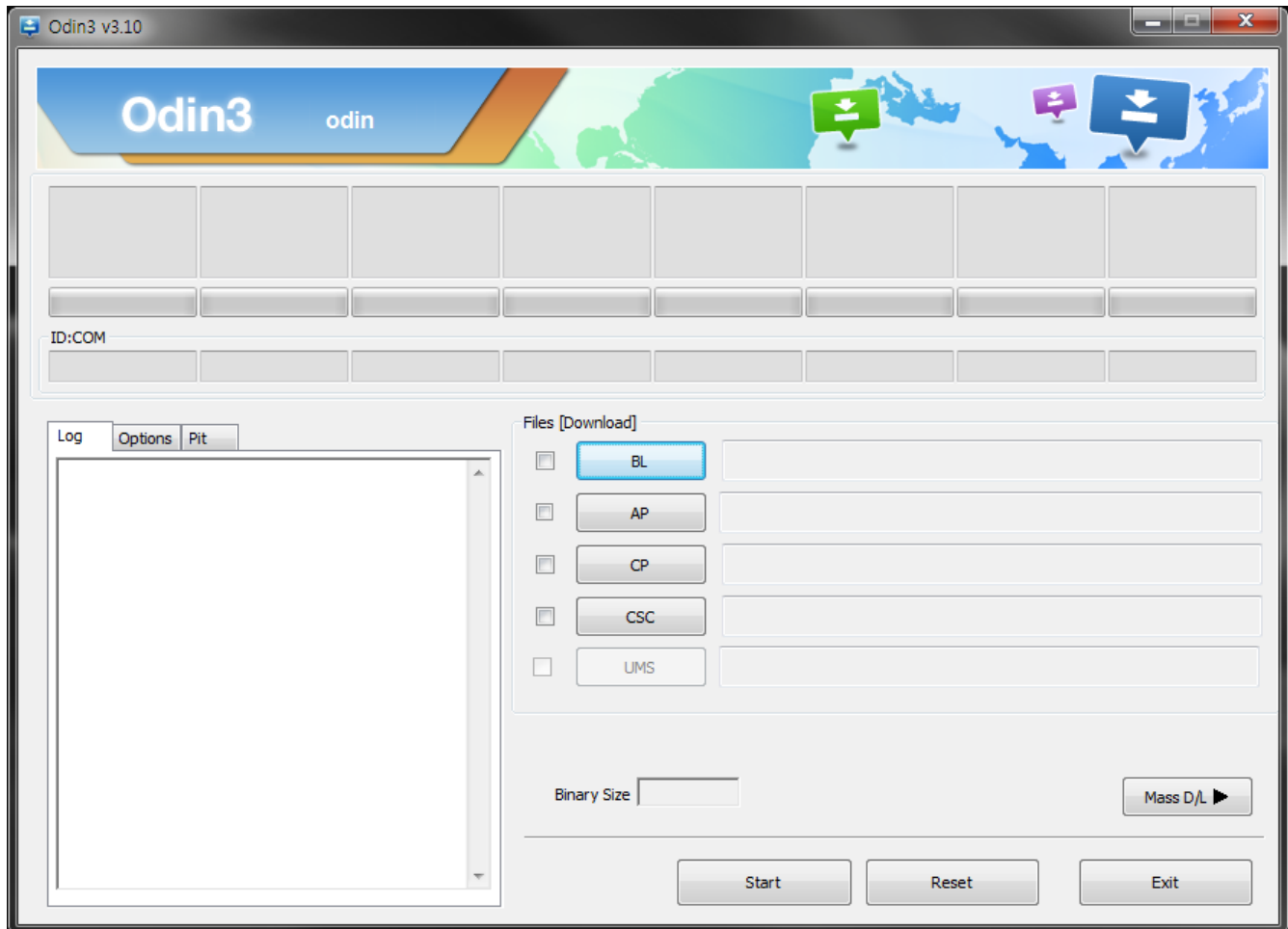
#### ※ Settings



Data Cable : GH39-01710C

## 6-1-2. S/W Installation Program (Downloader program)

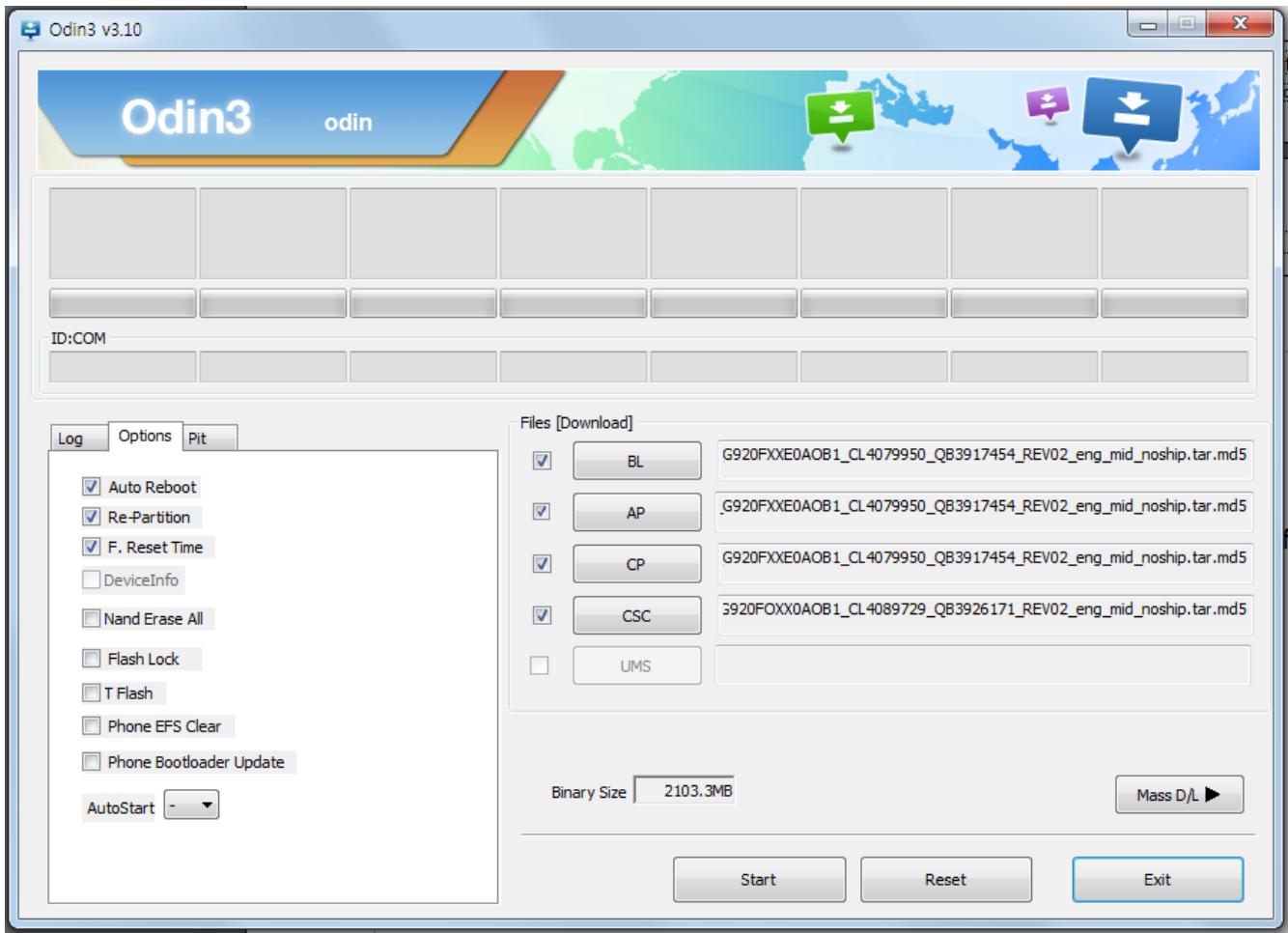
- Open up the S/W Installation Program by executing the "**Odin3 v3.10.6.exe**"



1. Enable the check mark by click on the following options,

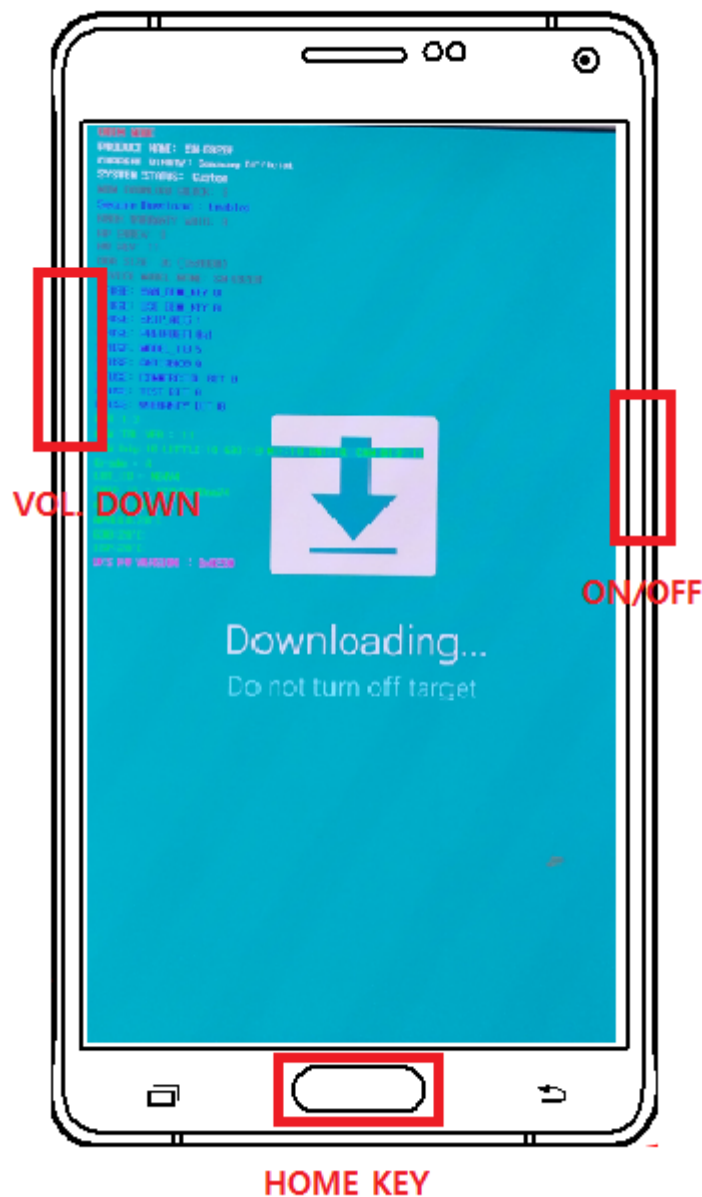
- Check Auto Reboot, Re-Partition, and F. Reset Time
- Check PIT
- Check BOOTLOADER, PDA, PHONE, and CSC Files

\* Note : "Odin v3.10 or above" checks MD5 checksum just after file selection.



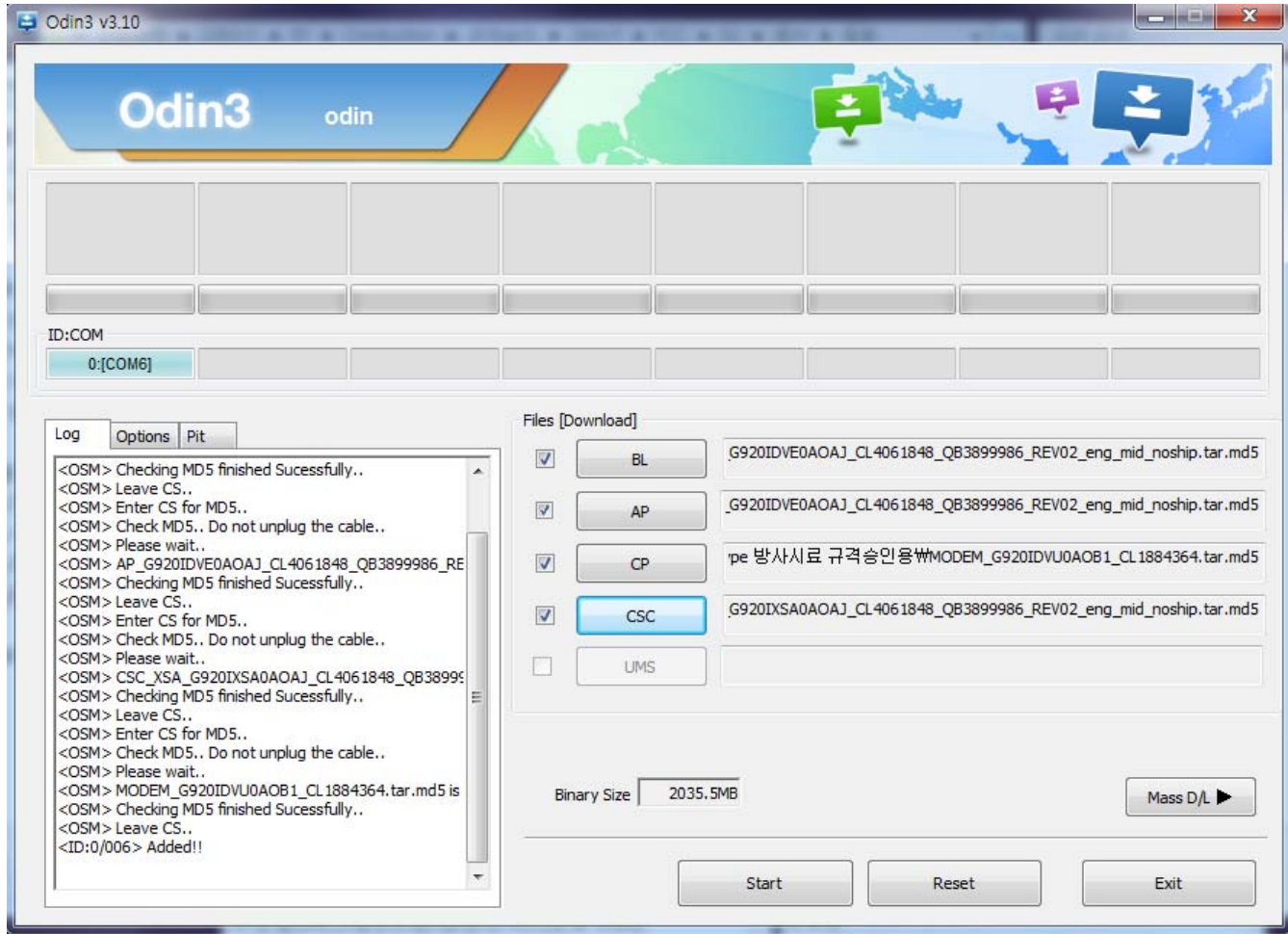
## 2. Enter into Download Mode

- Enter into Download Mode by pressing Volume Down button, Home button and ON/OFF Button simultaneously followed by pressing Volume up button as a direction of the phone.



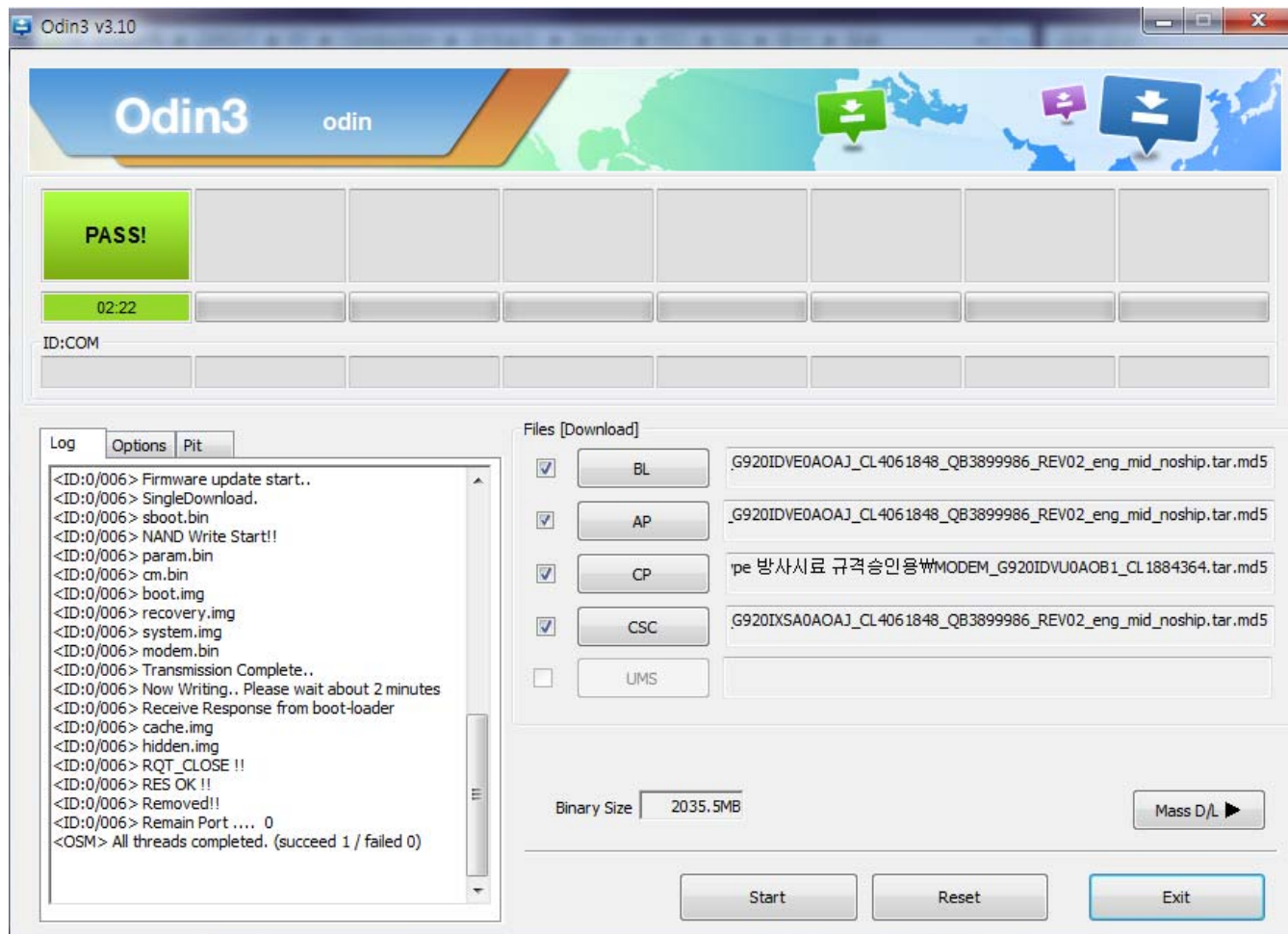
**3. Connect the device to PC via Data Cable.**

Make sure that the one of communication ports [ID:COM] box is highlighted in sky blue. The device is now connected with the PC and ready to download the binary files in it.





4. Start downloading the binary files into the device by clicking Start button on the screen. The green colored "PASS!" sign will appear on the upper-left box if the binary files have been successfully downloaded into the device.



5. Disconnect the device from the Data cable.
6. Once the device boots up, you can check the version of the binary file or name by pressing the following code in sequence;  
**\*#1234#**

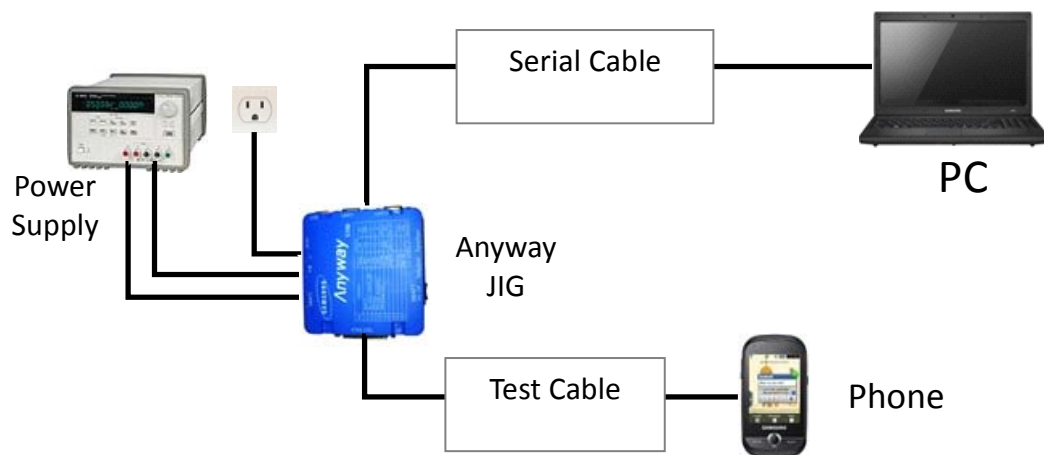
You can perform Factory Reset by Settings → Accounts → Backup and reset

## 6-2 IMEI writing

### 6-2-1 Preparation

- New IMEI writing Program has been released.
- Supported Model : Models which CAB files are uploaded on HHPsvc INI File category, instead of ini file.
- Refer to below IMEI writing procedure.

#### - H/W



#### - S/W

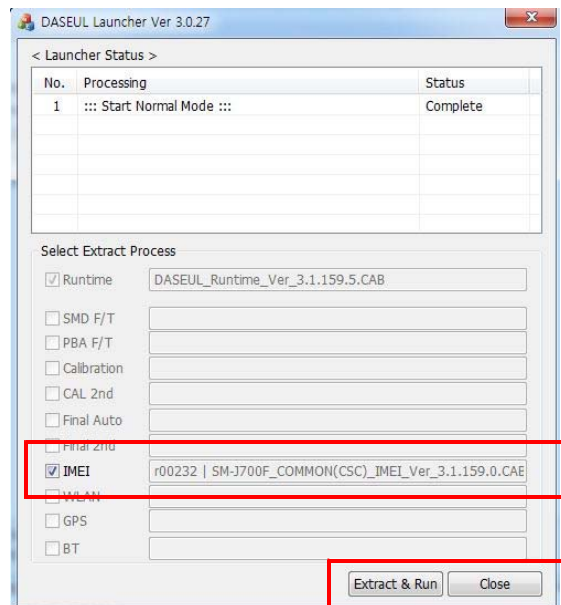
① Library Install	To use Daseul, library files should be installed. Refer to SVC Bulletin “(11-82) Daseul (New IMEI writing Program) Library Install guide_rev1.0”
② Launcher	DASEUL_SVC_Launcher_v3_0_25 or higher -Uploaded on HHPsvc Notice
③ Runtime File	1. DASEUL_Runtime_Ver_3.1.139.0.CAB or higher -Uploaded on HHPsvc Notice 2. Make 'ModelName' folder at the same position with launcher & Runtime file.
④ Model File	Copy Model File under the 'Model Name' folder

## 6-2-2 IMEI writing Process

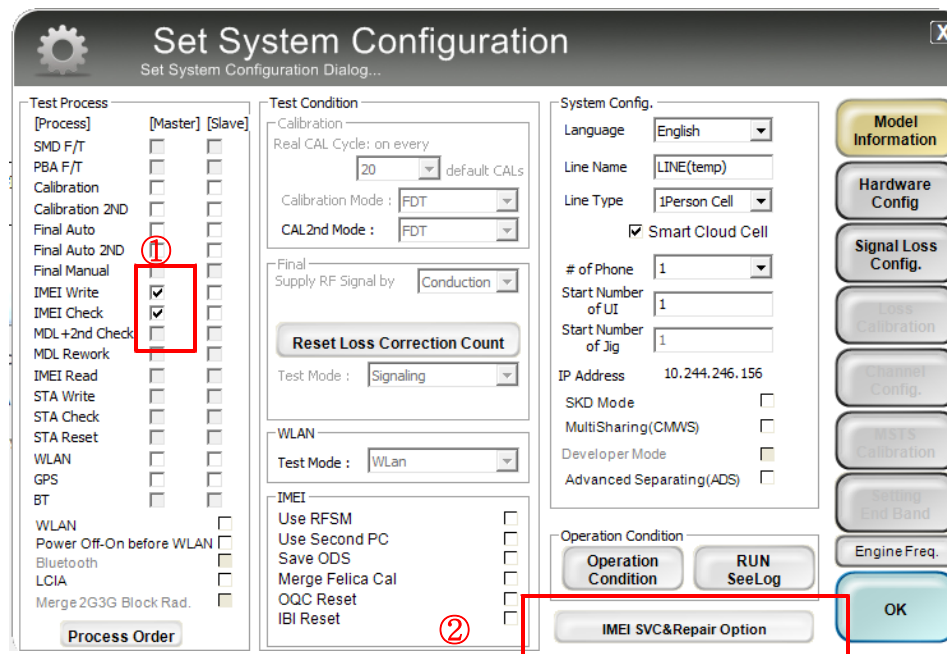
1. Run DASEUL\_SVC\_Launcher\_v3.0.10.exe



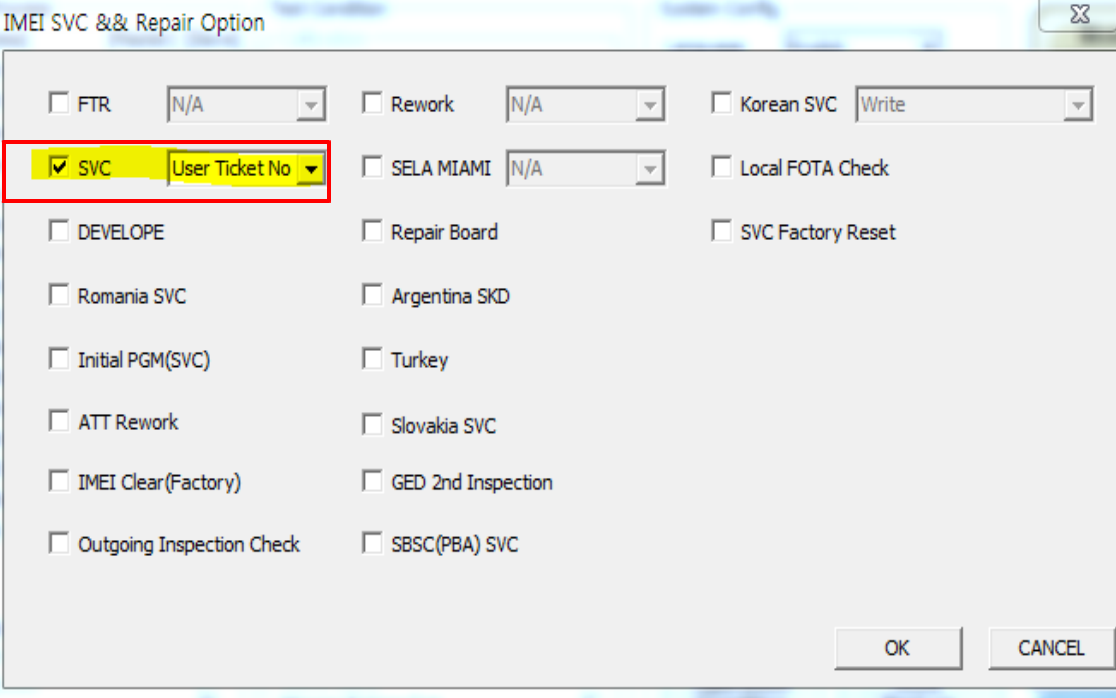
2. Select IMEI and then Extract & Run



3. Check 'IMEI Write / IMEI Check', and click 'IMEI SVC & Repair Option'

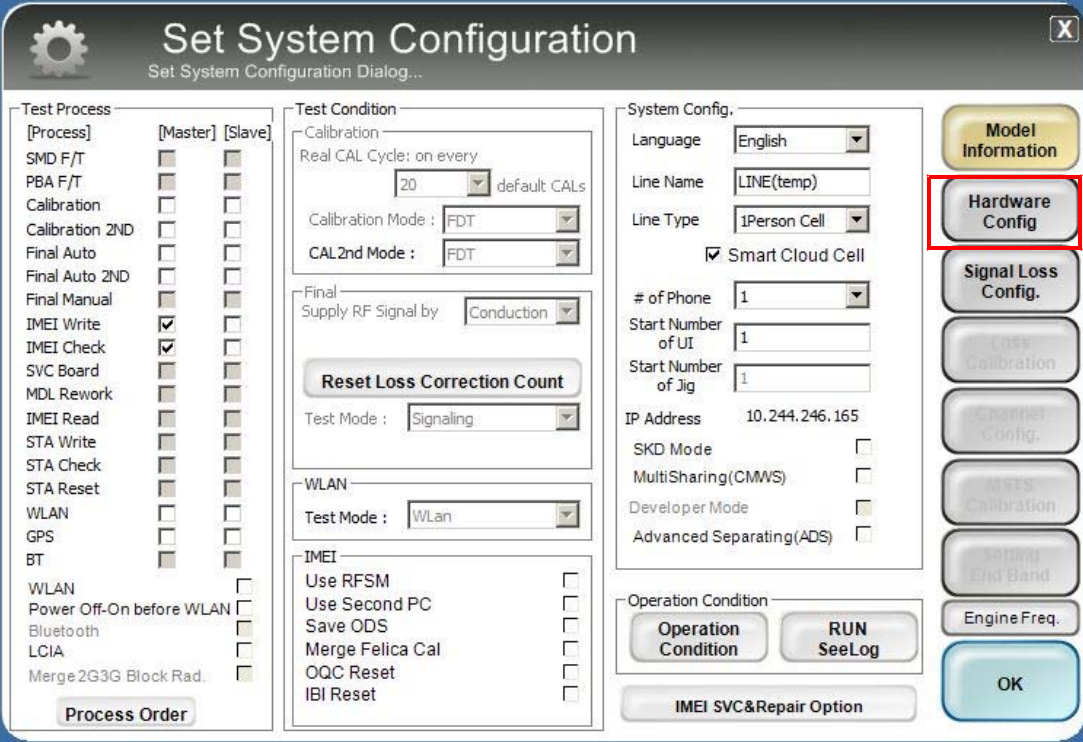


4. Check 'SVC , User Ticket No' and click OK



The dialog box titled "IMEI SVC && Repair Option" contains various service options. The "SVC" checkbox is checked, and the "User Ticket No" dropdown menu is highlighted with a red box. Other options include FTR, Rework, Korean SVC, Sela Miami, Local FOTA Check, DEVELOPE, Repair Board, SVC Factory Reset, Romania SVC, Argentina SKD, Initial PGM(SVC), Turkey, ATT Rework, Slovakia SVC, IMEI Clear(Factory), GED 2nd Inspection, Outgoing Inspection Check, and SBSC(PBA) SVC. The "OK" and "CANCEL" buttons are at the bottom right.

5. Click 'Hardware Config'



The "Set System Configuration" dialog box has multiple tabs. The "Hardware Config" tab is highlighted with a red box. Other tabs include Test Process, Test Condition, System Config, Model Information, Signal Loss Config, Loss Calibration, Channel Config, GPS Calibration, Setting End Band, and Engine Freq. The "Hardware Config" tab contains various settings for the device, including Language, Line Name, Line Type, Smart Cloud Cell, # of Phone, Start Number of UI, Start Number of Jig, IP Address, SKD Mode, MultiSharing(CMWS), Developer Mode, Advanced Separating(ADS), Operation Condition, and RUN SeeLog. The "IMEI SVC&Repair Option" button is at the bottom.

## 6. Click 'Port Setting'

**Hardware Component Configuration**  
Controller Type, IO Bus Type, Port Setting,....

**Phone**  
Count: 1  
I/F - 1 Type: Serial COM  
I/F - 2 Type: N/A  
IF Jig Type: AnyWayJig  
☐ Use ID Check JIG  
MSTS Count: 0  
I/F Type: GPIB

**MSTS Sharing Controller**  
Count: 0  
Control Type: N/A  
I/F Type: Serial COM  
Robot / ShieldBox Control Type: N/A  
I/F Type: Serial COM  
Power Supply I/F Type: GPIB

**DBMS**  
Server: HOME(GUMI)  
Type: Outside-Socket  
Barcode Reader Type: N/A  
I/F Type: Serial COM  
MES PN Sender Type: N/A

**PBA F/T**  
Function Test Jig: Port Setting  
NI-DAQ: Port Setting  
Power Detector: Port Setting  
HDMI JIG: Port Setting  
SMD F/T Type: N/A  
B'd Address: 5

**Buttons:** Port Setting (highlighted), SAVE, Cancel

## 7. Select Port Number and SAVE

**Set IO BUS Configuration**

**Phone IO Bus Setting**

**Common**

BaudRate	115200
Data Bit	8
Parity	No
Stop Bit	1

No	Port #1
1	1

**Buttons:** SAVE (highlighted), Cancel

8. Click OK to proceed

**Set System Configuration**  
Set System Configuration Dialog...

**Test Process**

[Process]	[Master]	[Slave]
SMD F/T	<input type="checkbox"/>	<input type="checkbox"/>
PBA F/T	<input type="checkbox"/>	<input type="checkbox"/>
Calibration	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto	<input type="checkbox"/>	<input type="checkbox"/>
Final Manual	<input type="checkbox"/>	<input type="checkbox"/>

**IMEI Process**

IMEI Write	<input checked="" type="checkbox"/>	<input type="checkbox"/>
IMEI Check	<input checked="" type="checkbox"/>	<input type="checkbox"/>
MDL +2nd Check	<input type="checkbox"/>	<input type="checkbox"/>
MDL Rework	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Read	<input type="checkbox"/>	<input type="checkbox"/>

WLAN ☐  
Power Off-On before WLAN ☐  
Bluetooth ☐

**Test Condition**

**Calibration**  
Real CAL Cycle: on every  default: CALs  
Calibration Mode:

**Final**  
Supply RF Signal by:   
Test Signal Mode:   
Developer Mode ☐

**IMEI**  
Use RFSM ☐  
Use Second PC ☐  
Save ODS ☐

**System Config.**

Language:   
Line Name:   
Line Type:   
# of Phone:   
Start Number of Jig:   
IP Address:

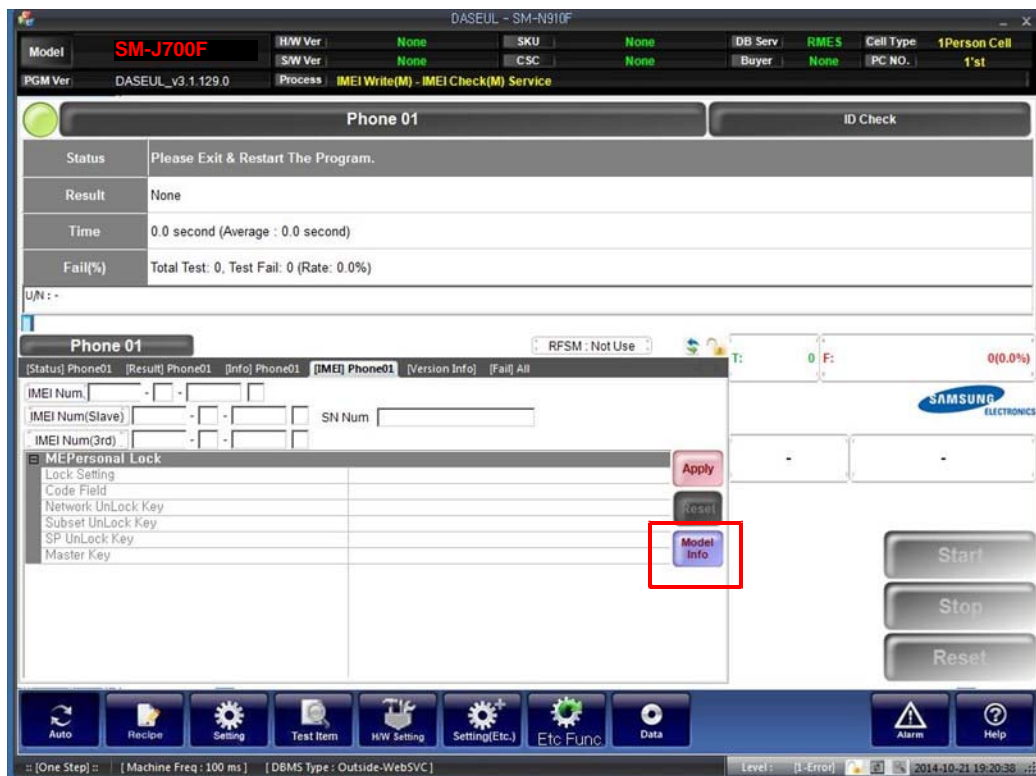
**Operation Condition**

**Model Information**  
**Hardware Config**  
**Signal Loss Config.**  
**Channel Config.**  
**Mass Calibration**  
**Testing End Band**

**IMEI SVC&Repair Option**  
**Operation Condition**  
**OK**



## 9. Click Model Info and OK when pop-up shows



## 13. Click OK



14. Input SKU\_CODE and BUYER, then click Save button.

※ Refer to HHPsvc→IMEI Review to check SKU Code and buyer

CSC	N098DCM1ANB5
PDA	N0980MU1ANB5
Software2	1
LPD	
Contents	
DMB	
SKU_CODE	SM-J700FEUROPEN
BUYER	DBT
Material_Code	
Boot	
Factory Software	N0980MU11&NR1

☐ 2nd Func Test (AT&T)    ☐ STA Option  
☐ FactoryReset+Check    ☐ Don't DB Upload    ☐ Tizen Download  
☐ Pre Product    ☐ Packing Rework    ☐ Android Download  
☐ Main Repair

Save Load Cancel

15. Input IMEI Number and click Apply

Model: SM-J700F    PGM Ver: DASEUL\_v3.1.129.0    Process: IMEI Write(M) - IMEI Check(M) Service

Phone 01    ID Check

Status: Please Exit & Restart The Program.  
 Result: None  
 Time: 0.0 second (Average : 0.0 second)  
 Fail(%): Total Test: 0, Test Fail: 0 (Rate: 0.0%)

Phone 01    RFSM: Not Use    0(0.0%)

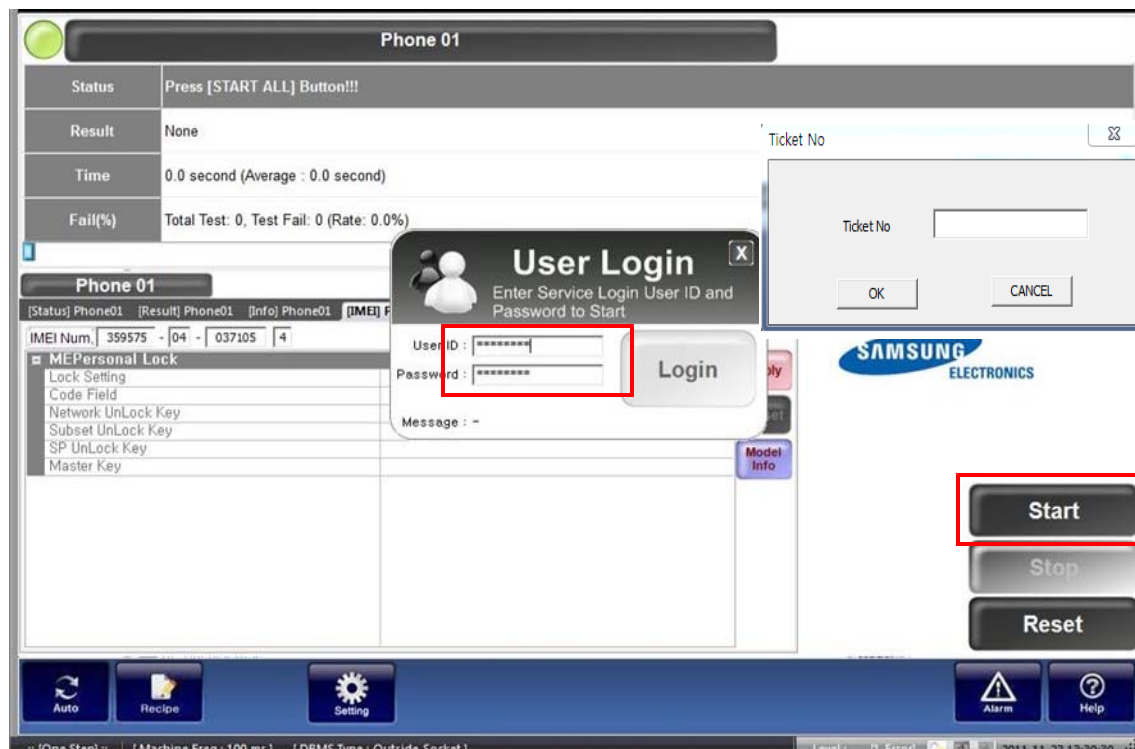
IMEI Num: 111111 11 111111    SN Num:    Apply

IMEI Num(2nd):    IMEIPersonal Lock:    Model Info

Auto    Recipe    Setting    Test Item    HW Setting    Setting(Etc.)    Etc Func    Data    Alarm    Help



16. ① Click Start, and input IMEI writing ID and Password → ② input Ticket No

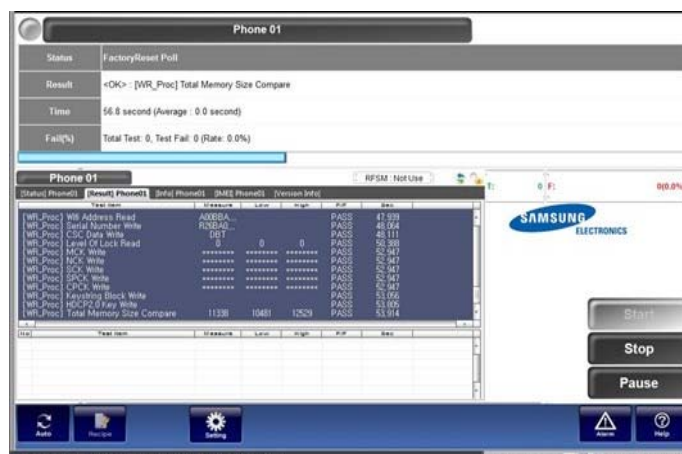


17. Connect the phone to Anyway JIG

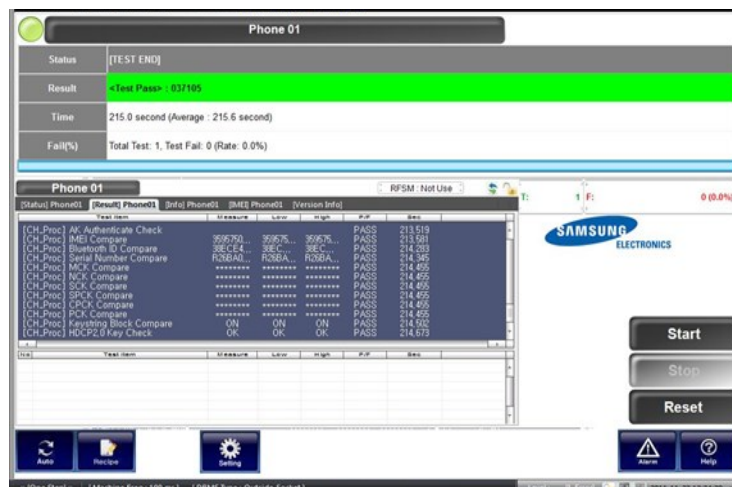
※ When you connect the phone, the phone should be turned off.

After connecting the phone, the phone will be booted automatically.

18. IMEI Writing Proceeding



## 19. IMEI Writing Success



## 6-4. RF Calibration

### 6-1-1. Required items in order to calibrate RF

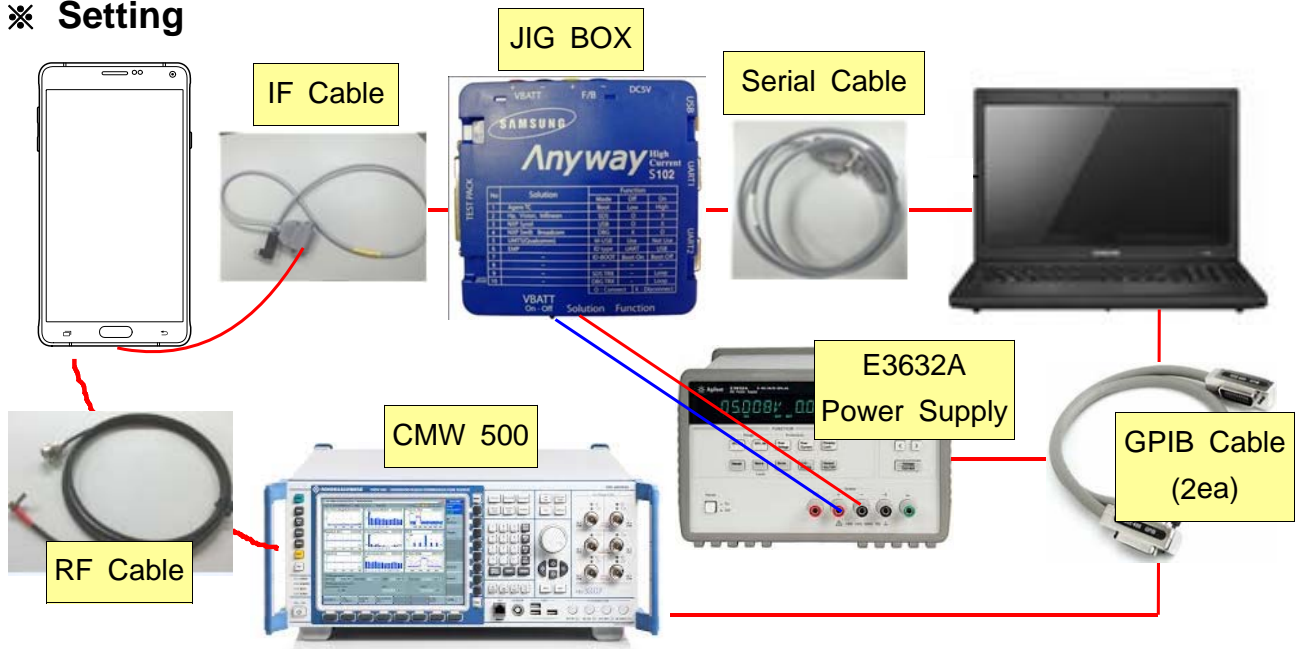
- Installation program: RF Calibration Program
  - Daseul\_Launcher\_vx.x.xx.exe
  - Daseul\_CAL\_ALL\_Runtime\_x.x.xxx.x.CAB
  - Model File (SM-XXXXX\_OPEN\_CALIBRATION\_VER\_x.x.xxx.xx.CAB)

※ It is required to use the latest program.

- Mobile Phone
- E3632A Power Supply
- JIG BOX (GH81-11888A)
- UART Serial Cable
- Table of test cables
- R&S CMW500
- GPIB Cable (2ea)
- Adapter (GH81-11888K)




IF Cable		GH81-10952A		
		7 pin		
RF Cable	GH81-11962G			
	Short			

## ※ Setting

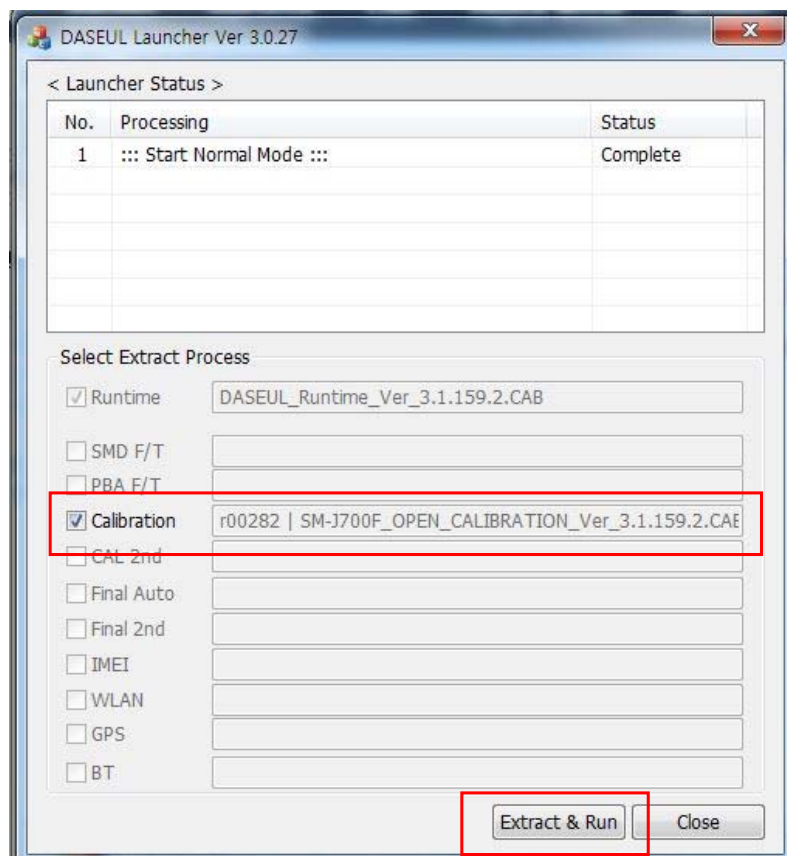


## 6-1-2. RF Calibration Program

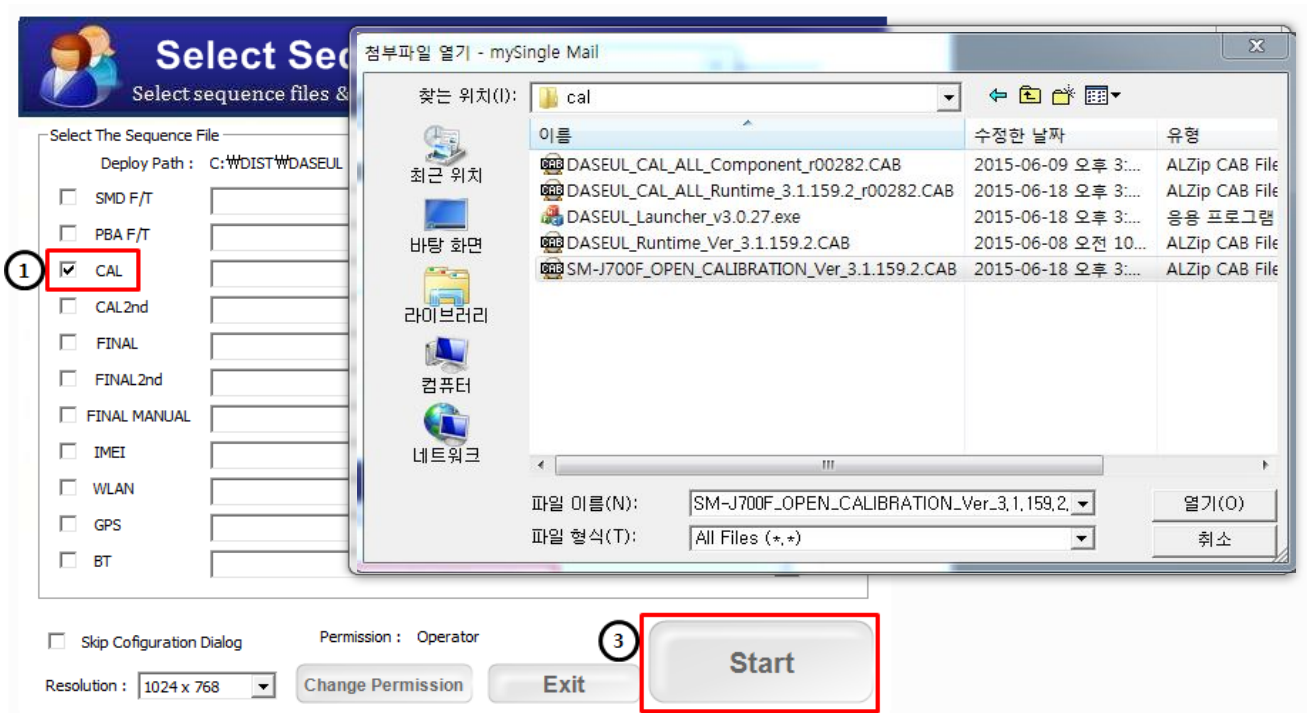
1. Run the RF Calibration Program Launcher, '[DASEUL\\_Launcher\\_vx.x.xx.exe](#)'.

 DASEUL\_Launcher\_v3.0.27.exe  
 DASEUL\_Runtime\_Ver\_3.1.159.2.CAB  
 SM-J700F\_OPEN\_CALIBRATION\_Ver\_3.1.159.2.CAB

2. Check the '[Calibration](#)' menu, and select '[Extract & Run](#)'.



3. Check the 'CAL' and open the [model file](#), then select 'Start' button.



4. Change the Line Type to 'Block Cell' and disable 'Smart Cloud Cell'.

**Set System Configuration**  
Set System Configuration Dialog...

**Test Process**

[Process]	[Master]	[Slave]
SMD F/T	<input type="checkbox"/>	<input type="checkbox"/>
PBA F/T	<input type="checkbox"/>	<input type="checkbox"/>
Calibration	<input checked="" type="checkbox"/>	<input type="checkbox"/>
Calibration 2ND	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto 2ND	<input type="checkbox"/>	<input type="checkbox"/>
Final Manual	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Write	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Check	<input type="checkbox"/>	<input type="checkbox"/>
MDL +2nd Check	<input type="checkbox"/>	<input type="checkbox"/>
MDL Rework	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Read	<input type="checkbox"/>	<input type="checkbox"/>
STA Write	<input type="checkbox"/>	<input type="checkbox"/>
STA Check	<input type="checkbox"/>	<input type="checkbox"/>
STA Reset	<input type="checkbox"/>	<input type="checkbox"/>
WLAN	<input type="checkbox"/>	<input type="checkbox"/>
GPS	<input type="checkbox"/>	<input type="checkbox"/>
BT	<input type="checkbox"/>	<input type="checkbox"/>
WLAN	<input type="checkbox"/>	<input type="checkbox"/>
Power Off-On before WLAN	<input type="checkbox"/>	<input type="checkbox"/>
Bluetooth	<input type="checkbox"/>	<input type="checkbox"/>
LCIA	<input type="checkbox"/>	<input type="checkbox"/>
Merge 2G3G Block Rad.	<input type="checkbox"/>	<input type="checkbox"/>

**Test Condition**

**Calibration**  
Real CAL Cycle: on every  default CALs

Calibration Mode :

CAL2nd Mode :

**Final**  
Supply RF Signal by :

- Loss Cal ☐

**Reset Loss Correction Count**

Test Mode :

**WLAN**  
Test Mode :

**IMEI**

Use RFSM	<input type="checkbox"/>
Use Second PC	<input type="checkbox"/>
Save ODS	<input type="checkbox"/>
Merge Felica Cal	<input type="checkbox"/>
OQC Reset	<input type="checkbox"/>
IBI Reset	<input type="checkbox"/>

**System Config.**

Language :

Line Name :

Line Type :

☐ Smart Cloud Cell

# of Phone :

Start Number of UI :

Start Number of Jig :

IP Address : 10.253.40.78

SKD Mode ☐

MultiSharing(CMWS) ☐

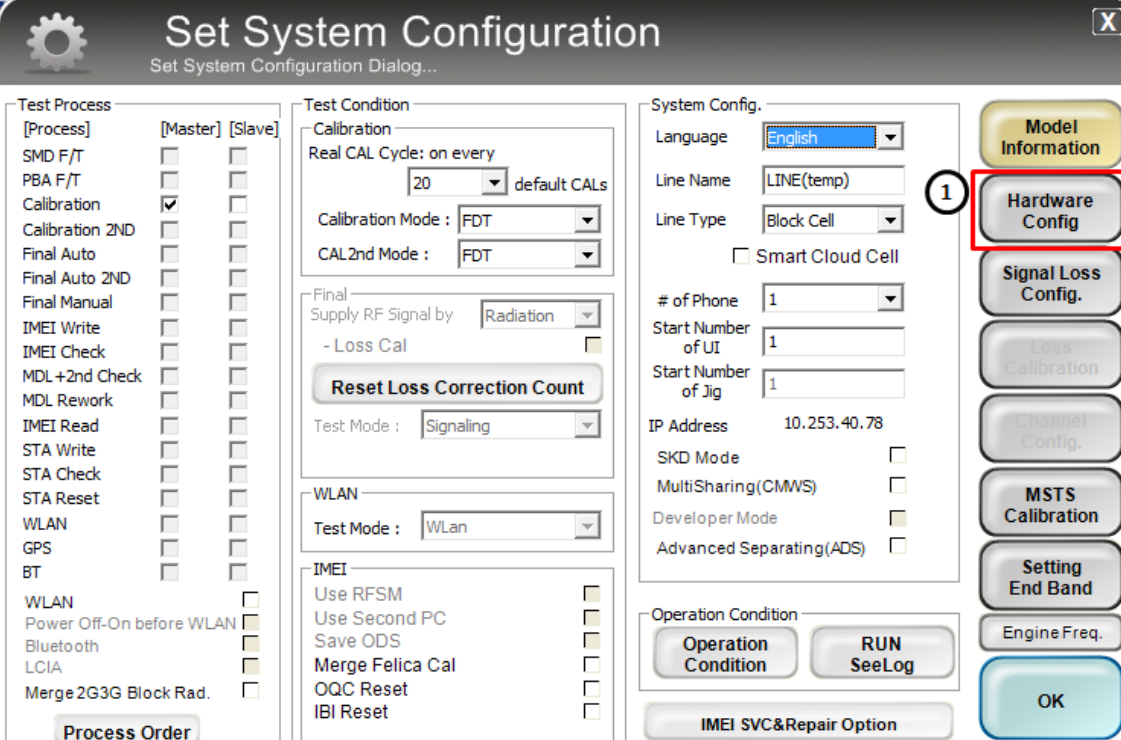
Developer Mode ☐

Advanced Separating(ADS) ☐

**Operation Condition**

**Model Information**

5. Set the GPIB address of MSTs(CMW500) and Power Supply(E3632A) to enter 'Hardware Config' and 'Save'. (Check the GPIB address of equipments in advance)



**Set System Configuration**  
Set System Configuration Dialog...

**Test Process**

[Process]	[Master]	[Slave]
SMD F/T	<input type="checkbox"/>	<input type="checkbox"/>
PBA F/T	<input type="checkbox"/>	<input type="checkbox"/>
Calibration	<input checked="" type="checkbox"/>	<input type="checkbox"/>
Calibration 2ND	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto	<input type="checkbox"/>	<input type="checkbox"/>
Final Auto 2ND	<input type="checkbox"/>	<input type="checkbox"/>
Final Manual	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Write	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Check	<input type="checkbox"/>	<input type="checkbox"/>
MDL+2nd Check	<input type="checkbox"/>	<input type="checkbox"/>
MDL Rework	<input type="checkbox"/>	<input type="checkbox"/>
IMEI Read	<input type="checkbox"/>	<input type="checkbox"/>
STA Write	<input type="checkbox"/>	<input type="checkbox"/>
STA Check	<input type="checkbox"/>	<input type="checkbox"/>
STA Reset	<input type="checkbox"/>	<input type="checkbox"/>
WLAN	<input type="checkbox"/>	<input type="checkbox"/>
GPS	<input type="checkbox"/>	<input type="checkbox"/>
BT	<input type="checkbox"/>	<input type="checkbox"/>
WLAN	<input type="checkbox"/>	<input type="checkbox"/>
Power Off-On before WLAN	<input type="checkbox"/>	<input type="checkbox"/>
Bluetooth	<input type="checkbox"/>	<input type="checkbox"/>
LCIA	<input type="checkbox"/>	<input type="checkbox"/>
Merge 2G3G Block Rad.	<input type="checkbox"/>	<input type="checkbox"/>

**Test Condition**

Calibration  
Real CAL Cycle: on every 20 default CALS

Calibration Mode: FDT  
CAL2nd Mode: FDT

Final Supply RF Signal by: Radiation  
- Loss Cal ☐  
**Reset Loss Correction Count**

Test Mode: Signaling

WLAN  
Test Mode: WLAN

IMEI  
Use RFSM ☐  
Use Second PC ☐  
Save ODS ☐  
Merge Felica Cal ☐  
OQC Reset ☐  
IBI Reset ☐

**System Config.**

Language: English  
Line Name: LINE(temp)  
Line Type: Block Cell  
☐ Smart Cloud Cell

# of Phone: 1  
Start Number of UI: 1  
Start Number of Jig: 1

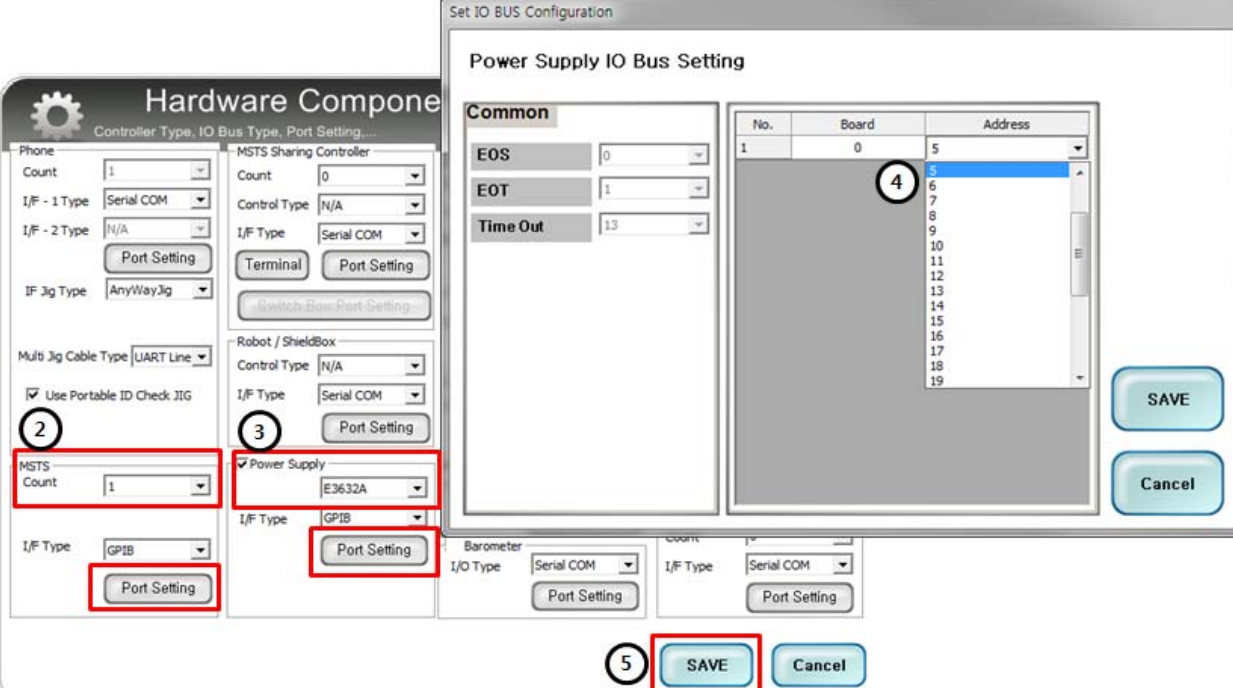
IP Address: 10.253.40.78

SKD Mode ☐  
MultiSharing(CMWS) ☐  
Developer Mode ☐  
Advanced Separating(ADS) ☐

**Operation Condition**  
Operation Condition RUN SeeLog

IMEI SVC&Repair Option

**Model Information**  
Hardware Config  
Signal Loss Config.  
Loss Calibration  
Channel Config.  
MSTS Calibration  
Setting End Band  
Engine Freq.  
OK



**Hardware Component**  
Controller Type, IO Bus Type, Port Setting...

Phone  
Count: 1  
I/F - 1 Type: Serial COM  
I/F - 2 Type: N/A  
IF Jig Type: AnyWayJig  
Multi Jig Cable Type: UART Line  
☒ Use Portable ID Check JIG

MSTS Sharing Controller  
Count: 0  
Control Type: N/A  
I/F Type: Serial COM  
Terminal Port Setting  
Switch Box Port Setting

Robot / ShieldBox  
Control Type: N/A  
I/F Type: Serial COM  
Port Setting

☒ Power Supply  
E3632A  
I/F Type: GPIB  
Port Setting

MSTS Count: 1  
I/F Type: GPIB  
Port Setting

**Power Supply IO Bus Setting**

**Common**

EOS: 0  
EOT: 1  
Time Out: 13

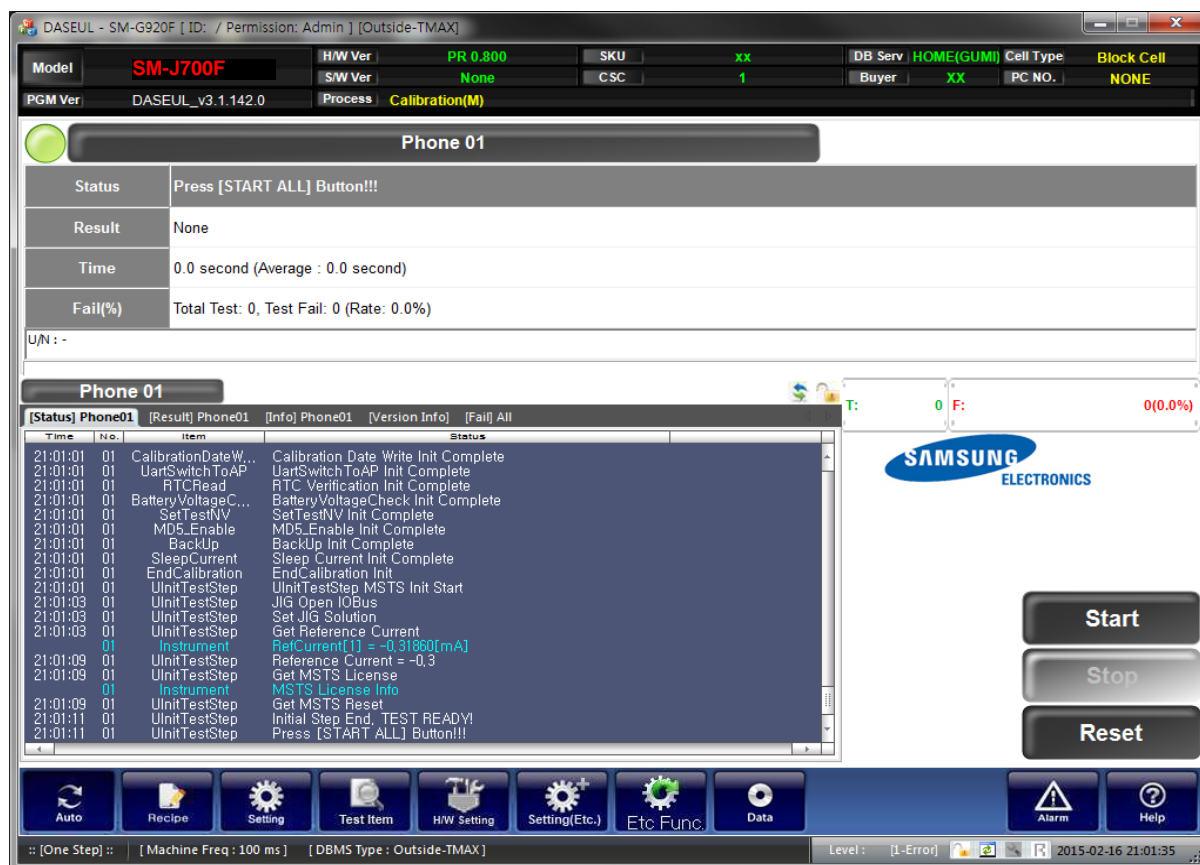
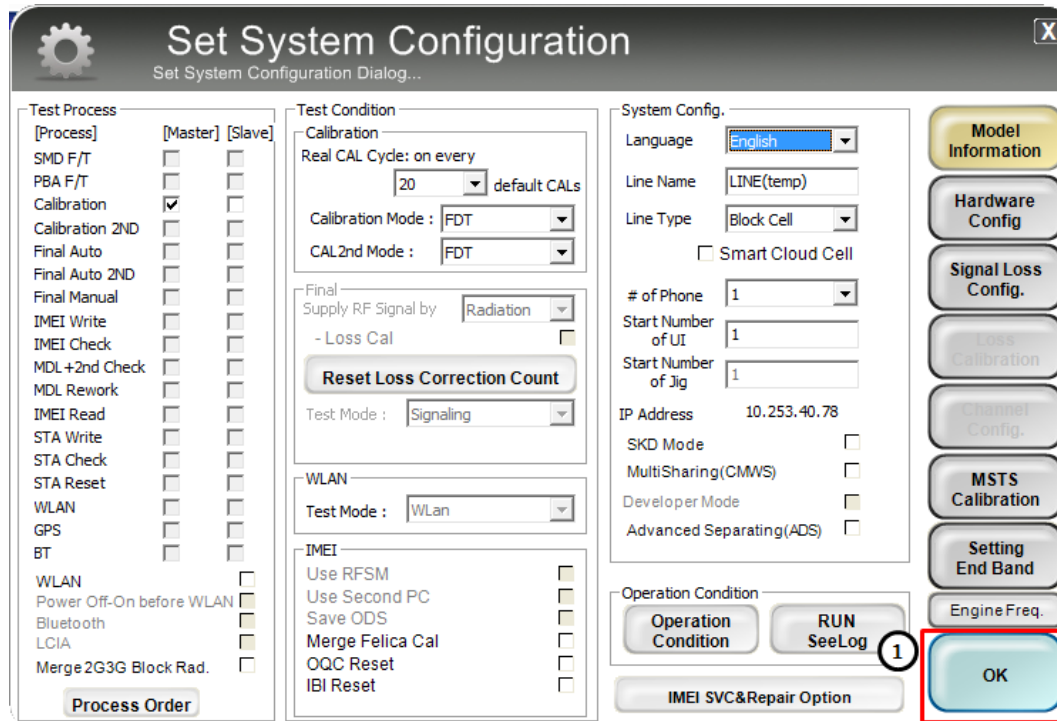
No.	Board	Address
1	0	5
2		
3		
4		
5		
6		
7		
8		
9		
10		
11		
12		
13		
14		
15		
16		
17		
18		
19		

SAVE Cancel

SAVE Cancel



6. Press 'OK' to start RF Calibration after completing all settings.

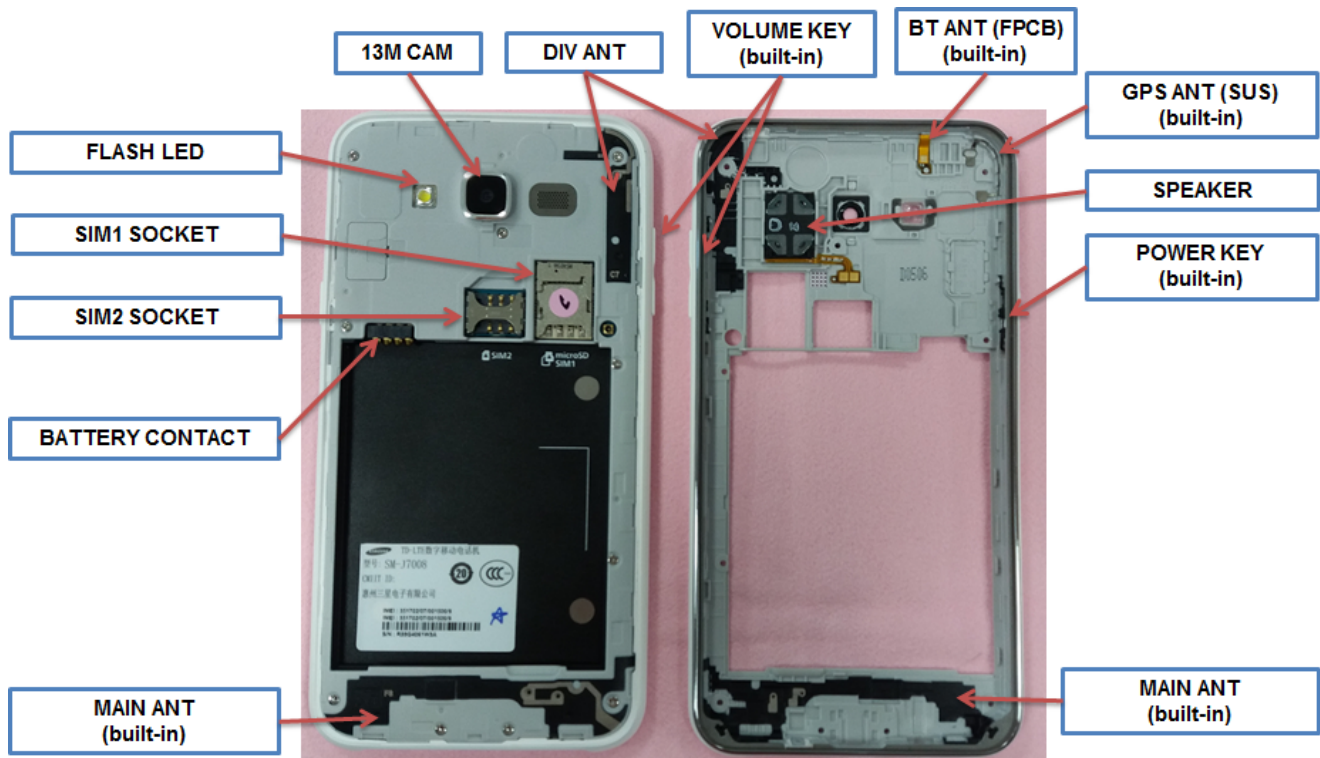


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## 7. Level 2 Repair

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### 7-1. Components on the Rear Case





## 7-2. Pre-requisite

	
<b>Tweezers / Disass'y Stick / Screw Driver</b>	<b>Anti-static Gloves</b>
	
<b>Anti-static Mat</b>	<b>Glass Absorber</b>
	
<b>OCTA Disassembly Holder</b>	<b>OCTA Disassembly Upper</b>
	
<b>Ethyl Alcohol</b>	<b>Clean Swab</b>

## 7-3. Disassembly

<div data-bbox="164 331 240 390">1</div> <div data-bbox="261 338 797 394"> <b>Apart LCD CAP from REAR</b> </div> 	<div data-bbox="841 348 917 407">2</div> <div data-bbox="943 338 1479 394"> <b>Loosen screw 10 points in the REAR</b> </div> 
<p>※ <b>Caution</b> 1) Be care of scratch</p>	<p>※ <b>Caution</b> -Torque : 1.2 Kgf · cm -Size : 1.4*3 (6001-003162)</p>
<div data-bbox="164 1146 240 1205">3</div> <div data-bbox="261 1136 797 1205"> <b>Detach LCD ass'y</b> </div> 	<div data-bbox="829 1146 906 1205">4</div> <div data-bbox="922 1136 1458 1205"> <b>Disassemble REAR and Bracket ass'y</b> </div> 
<p>※ <b>Caution</b> 1) Be care of damage to LCD TAPE on Bracket</p>	<p>※ <b>Caution</b> 1) Be care of damage to REAR Hook</p>

<div data-bbox="168 233 245 289">5</div> <div data-bbox="272 233 797 289">Disassemble PBA and Bracket ass'y</div>  The image shows the back of a smartphone with the PBA and bracket assembly highlighted by red circles. The assembly is located at the top and bottom of the device. The top circle highlights a small component, and the bottom circle highlights a larger component. The assembly is labeled with a blue 'C'.	<div data-bbox="836 233 912 289">6</div> <div data-bbox="940 233 1464 289">Disassemble PARTs</div>  The image shows the back of a smartphone with the PBA and bracket assembly highlighted by red circles. The assembly is located at the top and bottom of the device. The top circle highlights a small component, and the bottom circle highlights a larger component.
<p>※ <b>Caution</b></p> <ul style="list-style-type: none"><li>- Torque : 1.2 Kgf · cm</li><li>- Size : 1.4*2.3 (6001-003180)</li><li>- Be careful of the hook of bracket (1 point)</li></ul>	<p>※ <b>Caution</b></p> <ul style="list-style-type: none"><li>- Be careful of damage to Electric materials</li></ul>



## 7-5. Assembly

<div data-bbox="162 294 235 346" data-label="Text">1</div> <div data-bbox="259 294 787 346" data-label="Section-Header">Assemble LCD &amp; TSP</div> <div data-bbox="316 367 630 930" data-label="Image"> </div>	<div data-bbox="828 294 901 346" data-label="Text">2</div> <div data-bbox="933 294 1461 346" data-label="Section-Header">Assemble Bracket Ass'y</div> <div data-bbox="836 367 1429 930" data-label="Image"> </div>
<p>※ <b>Caution</b></p> <p>1) Be care of FPCB</p> <p>2) Don't forget to connect TSP FPCB Conn.</p>	<p>※ <b>Caution</b></p> <p>- Be care of scratch and molding damage</p>
<div data-bbox="162 1102 235 1155" data-label="Text">3</div> <div data-bbox="259 1102 787 1155" data-label="Section-Header">Assemble PBA and Front Ass'y</div> <div data-bbox="316 1176 630 1711" data-label="Image"> </div>	<div data-bbox="828 1102 901 1155" data-label="Text">4</div> <div data-bbox="933 1102 1461 1155" data-label="Section-Header">Assemble REAR Ass'y</div> <div data-bbox="990 1176 1282 1711" data-label="Image"> </div>
<p>※ <b>Caution</b></p> <p>1) Be care of Torque:1.2 Kgf*cm</p> <p>2) Combine the Bracket hook 1 point correctly.</p>	<p>※ <b>Caution</b></p> <p>1) Be care of damage to the FPCB</p>

<div data-bbox="167 262 792 317"> <div>5</div> <div>Assemble REAR Ass'y and Front ass'y</div> </div> <div data-bbox="326 338 638 894"> </div>	<div data-bbox="826 262 1451 317"> <div>6</div> <div>Assemble LCD ass'y and REAR ass'y</div> </div> <div data-bbox="984 327 1287 884"> </div>
<div data-bbox="167 957 654 1020"> <p>※ <b>Caution</b></p> <p>1) Be care of Torque:1.2 Kgf*cm</p> </div>	<div data-bbox="826 915 1463 1052"> <p>※ <b>Caution</b></p> <ol style="list-style-type: none"> <li>1. Insert LCD Connector into the bracket hole correctly.</li> <li>2. Insert RCV deco into the TSP hole correctly.</li> <li>3. Attach LCD ass'y and Bracket ass'y.</li> </ol> </div>
<div data-bbox="167 1077 792 1131"> <div>7</div> <div>Assemble LCD CAP</div> </div> <div data-bbox="329 1169 639 1726"> </div>	
<div data-bbox="167 1776 488 1839"> <p>※ <b>Caution</b></p> <p>1) Be care of Scratch</p> </div>	

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